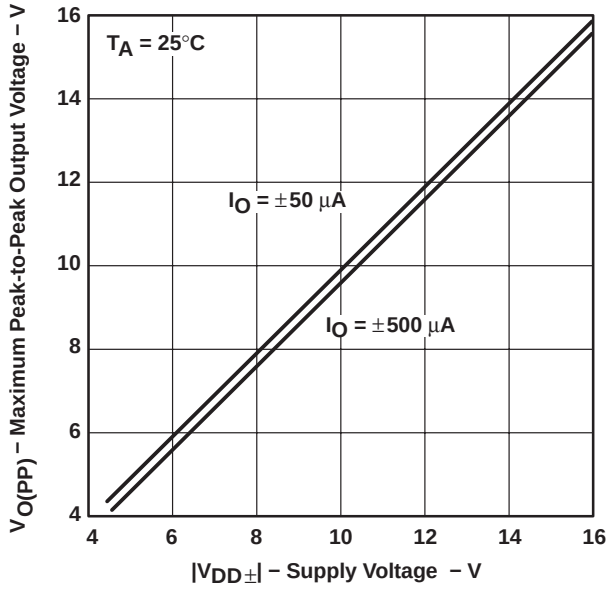
- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Extended Temperature Performance of −55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree†**
- **Output Swing Includes Both Supply Rails**
- **Low Noise . . . 9 nV/√Hz Typ at f = 1 kHz**
- **Low Input Bias Current . . . 1 pA Typ**
- **Fully Specified for Both Single-Supply and Split-Supply Operation**
- **Common-Mode Input Voltage Range Includes Negative Rail**
- **High-Gain Bandwidth . . . 2.2 MHz Typ**
- **High Slew Rate . . . 3.6 V/μs Typ**
- **Low Input Offset Voltage 950 μV Max at T_A = 25°C**
- **Macromodel Included**
- **Performance Upgrades for the TS272, TS274, TLC272, and TLC274**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs SUPPLY VOLTAGE



description

The TLC2272A and TLC2274A are dual and quadruple operational amplifiers from Texas Instruments. Both devices exhibit rail-to-rail output performance for increased dynamic range in single- or split-supply applications. The TLC227xA family offers 2 MHz of bandwidth and 3 V/μs of slew rate for higher speed applications. These devices offer comparable ac performance while having better noise, input offset voltage, and power dissipation than existing CMOS operational amplifiers. The TLC227xA has a noise voltage of 9 nV/√Hz, two times lower than competitive solutions.

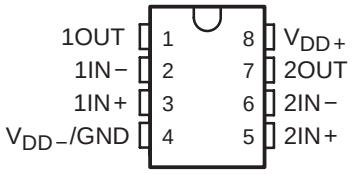
The TLC227xA, exhibiting high input impedance and low noise, is excellent for small-signal conditioning for high-impedance sources, such as piezoelectric transducers. Because of the micro-power dissipation levels, these devices work well in hand-held monitoring and remote-sensing applications. In addition, the rail-to-rail output feature, with single- or split-supplies, makes this family a great choice when interfacing with analog-to-digital converters (ADCs). For precision applications, the TLC227xA family has a maximum input offset voltage of 950 μV. This family is fully characterized at 5 V and ±5 V.

The TLC2272/4 also makes great upgrades to the TLC272/4 or TS272/4 in standard designs. They offer increased output dynamic range, lower noise voltage, and lower input offset voltage. This enhanced feature set allows them to be used in a wider range of applications.

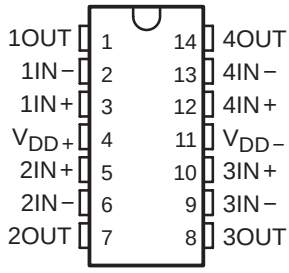
AVAILABLE OPTIONS

T_A	V_{IO}max At 25°C	PACKAGED DEVICES	
		SMALL OUTLINE (D)	TSSOP (PW)
−55°C to 125°C	950 µV 2.5 mV	TLC2272AMDREP TLC2272MDREP	TLC2272AMPWREP TLC2272MPWREP
−55°C to 125°C	950 µV 2.5 mV	TLC2274AMDREP TLC2274MDREP	TLC2274AMPWREP TLC2274MPWREP

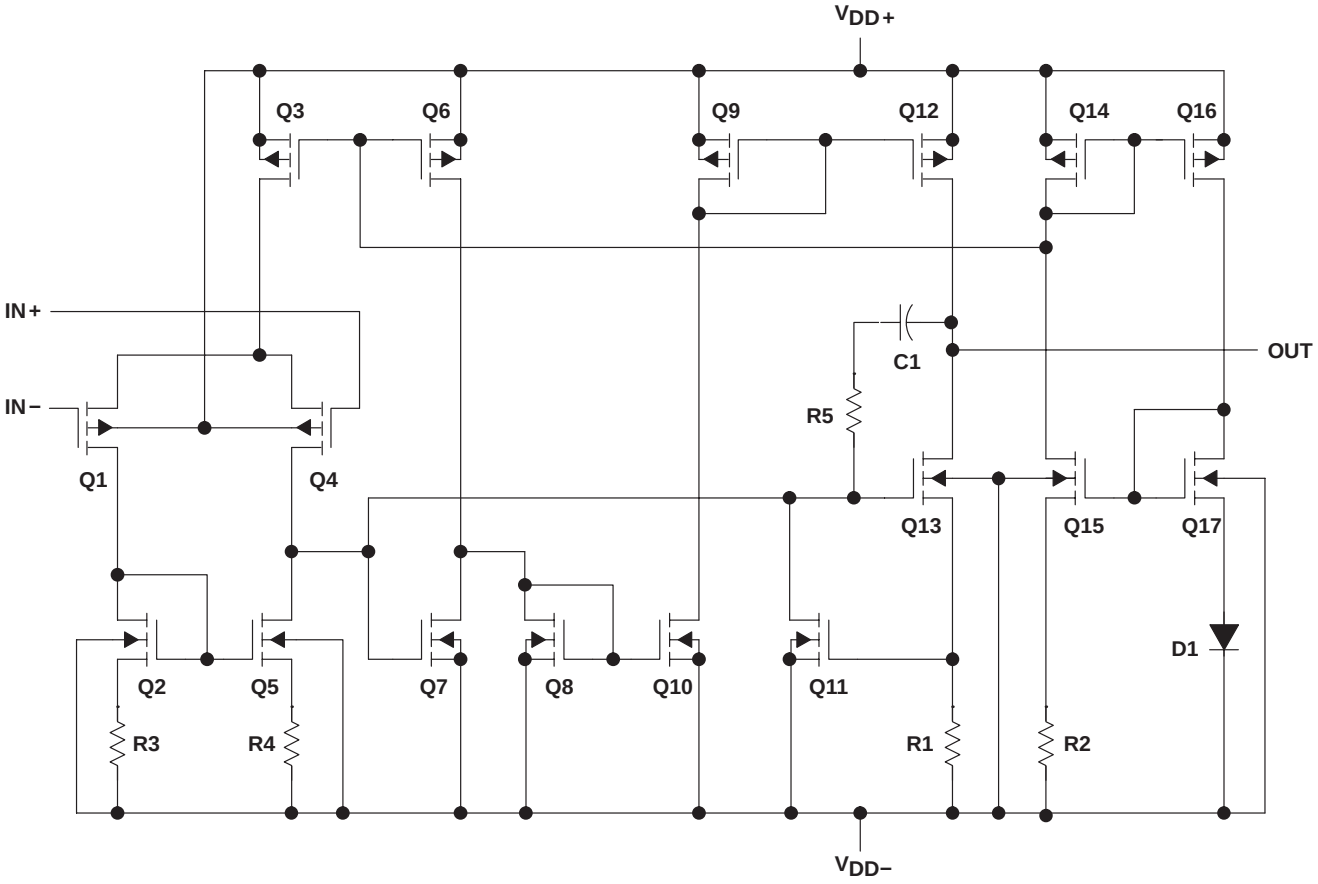
TLC2272
D OR PW PACKAGE
(TOP VIEW)



TLC2274
D OR PW PACKAGE
(TOP VIEW)



equivalent schematic (each amplifier)



ACTUAL DEVICE COMPONENT COUNT†		
COMPONENT	**TLC2272**	**TLC2274**
Transistors	38	76
Resistors	26	52
Diodes	9	18
Capacitors	3	6

† Includes both amplifiers and all ESD, bias, and trim circuitry

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD+} (see Note 1) . . . . . 8 V
Supply voltage, V_{DD-} (see Note 1) . . . . . −8 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±16 V
Input voltage range, V_I (any input, see Note 1) . . . . . V_{DD-} − 0.3 V to V_{DD+}
Input current, I_I (any input) . . . . . ±5 mA
Output current, I_O . . . . . ±50 mA
Total current into V_{DD+} . . . . . ±50 mA
Total current out of V_{DD-} . . . . . ±50 mA
Duration of short-circuit current at (or below) 25°C (see Note 3) . . . . . unlimited
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . −55°C to 125°C
Storage temperature range (see Note 4) . . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or PW package . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{DD+} and V_{DD-}.
2. Differential voltages are at IN+ with respect to IN−. Excessive current will flow if input is brought below V_{DD-} − 0.3 V.
3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
4. Long term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D-8	725 mW	5.8 mW/°C	464 mW	337 mW	145 mW
D-14	950 mW	7.6 mW/°C	608 mW	494 mW	190 mW
PW-8	525 mW	4.2 mW/°C	336 mW	273 mW	105 mW
PW-14	700 mW	5.6 mW/°C	448 mW	364 mW	—

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, $V_{DD\pm}$	±2.2	±8	V
Input voltage, V_I	V_{DD-}	V_{DD+} −1.5	V
Common-mode input voltage, V_{IC}	V_{DD-}	V_{DD+} −1.5	V
Operating free-air temperature, T_A	−55	125	°C

TLC2272-EP electrical characteristics at specified free-air temperature, V_{DD} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	TLC2272-EP			TLC2272A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{IC} = 0 V, V_O = 0 V,	$V_{DD\pm}$ = ±2.5 V, R_S = 50 Ω	25°C		300	2500		300	950	μV
				Full range			3000			1500	
α_{VIO}	Temperature coefficient of input offset voltage			25°C to 125°C		2			2		μV/°C
	Input offset voltage long-term drift (see Note 5)			25°C		0.002			0.002		μV/mo
I_{IO}	Input offset current			25°C		0.5	60		0.5	60	pA
				Full range			800			800	
I_{IB}	Input bias current			25°C		1	60		1	60	pA
				Full range			800			800	
V_{ICR}	Common-mode input voltage	R_S = 50 Ω,	$\lvert V_{IO}\rvert \le$ 5 mV	25°C	0 to 4	−0.3 to 4.2		0 to 4	−0.3 to 4.2		V
				Full range	0 to 3.5			0 to 3.5			
V_{OH}	High-level output voltage	I_{OH} = −20 μA		25°C		4.99			4.99		V
		I_{OH} = −200 μA		25°C	4.85	4.93		4.85	4.93		
				Full range	4.85			4.85			
		I_{OH} = −1 mA		25°C	4.25	4.65		4.25	4.65		
				Full range	4.25			4.25			
V_{OL}	Low-level output voltage	V_{IC} = 2.5 V,	I_{OL} = 50 μA	25°C		0.01			0.01		V
		V_{IC} = 2.5 V,	I_{OL} = 500 μA	25°C		0.09	0.15		0.09	0.15	
				Full range			0.15			0.15	
		V_{IC} = 2.5 V,	I_{OL} = 5 mA	25°C		0.9	1.5		0.9	1.5	
				Full range			1.5			1.5	
A_{VD}	Large-signal differential voltage amplification	V_{IC} = 2.5 V, V_O = 1 V to 4 V	R_L = 10 kΩ‡	25°C	10	35		10	35		V/mV
				Full range	10			10			
			R_L = 1 mΩ‡	25°C		175			175		
r_{id}	Differential input resistance			25°C		10^{12}			10^{12}		Ω
r_i	Common-mode input resistance			25°C		10^{12}			10^{12}		Ω
c_i	Common-mode input capacitance	f = 10 kHz,	P package	25°C		8			8		pF
z_o	Closed-loop output impedance	f = 1 MHz,	A_V = 10	25°C		140			140		Ω
CMRR	Common-mode rejection ratio	V_{IC} = 0 V to 2.7 V, V_O = 2.5 V,	R_S = 50 Ω	25°C	70	75		70	75		dB
				Full range	70			70			
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{DD}/\Delta V_{IO}$)	V_{DD} = 4.4 V to 16 V, V_{IC} = V_{DD}/2,	No load	25°C	80	95		80	95		dB
				Full range	80			80			
I_{DD}	Supply current	V_O = 2.5 V,	No load	25°C		2.2	3		2.2	3	mA
				Full range			3			3	

† Full range is −55°C to 125°C for M level part.
‡ Referenced to 2.5 V
NOTE 5: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.

TLC2272-EP operating characteristics at specified free-air temperature, V_{DD} = 5 V

PARAMETER		TEST CONDITIONS		T_A†	TLC2272-EP			TLC2272A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
SR	Slew rate at unity gain	V_O = 1.25 V to 2.75 V, R_L = 10 kΩ‡, C_L = 100 pF‡		25°C	2.3	3.6		2.3	3.6		V/μs
				Full range	1.7			1.7			
V_n	Equivalent input noise voltage	f = 10 Hz		25°C		50			50		nV/√Hz
		f = 1 kHz		25°C		9			9		
V_{NPP}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C		1			1		μV
		f = 0.1 Hz to 10 Hz		25°C		1.4			1.4		
I_n	Equivalent input noise current			25°C		0.6			0.6		fA/√Hz
THD + N	Total harmonic distortion plus noise	V_O = 0.5 V to 2.5 V, f = 20 kHz, R_L = 10 kΩ‡,	A_V = 1	25°C		0.0013%			0.0013%		
			A_V = 10			0.004%			0.004%		
			A_V = 100			0.03%			0.03%		
	Gain-bandwidth product	f = 10 kHz, R_L = 10 kΩ‡, C_L = 100 pF‡		25°C		2.18			2.18		MHz
B_{OM}	Maximum output-swing bandwidth	$V_{O(PP)}$ = 2 V, A_V = 1, R_L = 10 kΩ‡, C_L = 100 pF‡		25°C		1			1		MHz
t_s	Settling time	A_V = −1, Step = 0.5 V to 2.5 V, R_L = 10 kΩ‡, C_L = 100 pF‡	To 0.1%	25°C		1.5			1.5		μs
			To 0.01%			2.6			2.6		
ϕ_m	Phase margin at unity gain	R_L = 10 kΩ‡, C_L = 100 pF‡		25°C		50°			50°		
	Gain margin			25°C		10			10		dB

† Full range is −55°C to 125°C for M level part.
‡ Referenced to 2.5 V

TLC2272-EP electrical characteristics at specified free-air temperature, $V_{DD\pm}$ = ±5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	TLC2272-EP			TLC2272A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{IC} = 0 V, V_O = 0 V, R_S = 50 Ω		25°C		300	2500		300	950	μV
				Full range			3000			1500	
α_{VIO}	Temperature coefficient of input offset voltage			25°C to 125°C		2			2		μV/°C
	Input offset voltage long-term drift (see Note 5)			25°C		0.002			0.002		μV/mo
I_{IO}	Input offset current			25°C		0.5	60		0.5	60	pA
				Full range			800			800	
I_{IB}	Input bias current			25°C		1	60		1	60	pA
				Full range			800			800	
V_{ICR}	Common-mode input voltage	R_S = 50 Ω,	$\lvert V_{IO}\rvert \le$ 5 mV	25°C	−5 to 4	−5.3 to 4.2		−5 to 4	−5.3 to 4.2		V
				Full range	−5 to 3.5			−5 to 3.5			
V_{OM+}	Maximum positive peak output voltage	I_O = −20 μA		25°C		4.99			4.99		V
		I_O = −200 μA		25°C	4.85	4.93		4.85	4.93		
				Full range	4.85			4.85			
		I_O = −1 mA		25°C	4.25	4.65		4.25	4.65		
				Full range	4.25			4.25			
V_{OM-}	Maximum negative peak output voltage	V_{IC} = 0 V,	I_O = 50 μA	25°C		−4.99			−4.99		V
		V_{IC} = 0 V,	I_O = 500 μA	25°C	−4.85	−4.91		−4.85	−4.91		
				Full range	−4.85			−4.85			
		V_{IC} = 0 V,	I_O = 5 mA	25°C	−3.5	−4.1		−3.5	−4.1		
				Full range	−3.5			−3.5			
A_{VD}	Large-signal differential voltage amplification	V_O = ±4 V	R_L = 10 kΩ	25°C	20	50		20	50		V/mV
				Full range	20			20			
			R_L = 1 mΩ	25°C		300			300		
r_{id}	Differential input resistance			25°C		10^{12}			10^{12}		Ω
r_i	Common-mode input resistance			25°C		10^{12}			10^{12}		Ω
c_i	Common-mode input capacitance	f = 10 kHz,	P package	25°C		8			8		pF
z_o	Closed-loop output impedance	f = 1 MHz,	A_V = 10	25°C		130			130		Ω
CMRR	Common-mode rejection ratio	V_{IC} = −5 V to 2.7 V, V_O = 0 V,	R_S = 50 Ω	25°C	75	80		75	80		dB
				Full range	75			75			
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{DD\pm}/\Delta V_{IO}$)	V_{DD} = ±2.2 V to ±8 V, V_{IC} = 0 V,	No load	25°C	80	95		80	95		dB
				Full range	80			80			
I_{DD}	Supply current	V_O = 2.5 V,	No load	25°C		2.4	3		2.4	3	mA
				Full range			3			3	

† Full range is −55°C to 125°C for M level part.

NOTE 5: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.

TLC2272-EP operating characteristics at specified free-air temperature, $V_{DD\pm}$ = ±5 V

PARAMETER		TEST CONDITIONS		T_A†	TLC2272-EP			TLC2272A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
SR	Slew rate at unity gain	V_O = ±1 V, C_L = 100 pF, R_L = 10 kΩ,		25°C	2.3	3.6		2.3	3.6		V/μs
				Full range	1.7			1.7			
V_n	Equivalent input noise voltage	f = 10 Hz		25°C		50			50		nV/√Hz
		f = 1 kHz		25°C		9			9		
V_{NPP}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C		1			1		μV
		f = 0.1 Hz to 10 Hz		25°C		1.4			1.4		
I_n	Equivalent input noise current			25°C		0.6			0.6		fA/√Hz
THD + N	Total harmonic distortion plus noise	V_O = ±2.3 V, R_L = 10 kΩ, f = 20 kHz	A_V = 1	25°C		0.0011%			0.0011%		
			A_V = 10			0.004%			0.004%		
			A_V = 100			0.03%			0.03%		
	Gain-bandwidth product	f = 10 kHz, C_L = 100 pF,	R_L = 10 kΩ,	25°C		2.25			2.25		MHz
B_{OM}	Maximum output-swing bandwidth	$V_{O(PP)}$ = 4.6 V, R_L = 10 kΩ,	A_V = 1, C_L = 100 pF	25°C		0.54			0.54		MHz
t_s	Settling time	A_V = −1, Step = −2.3 V to 2.3 V, R_L = 10 kΩ, C_L = 100 pF	To 0.1%	25°C		1.5			1.5		μs
			To 0.01%			3.2			3.2		
ϕ_m	Phase margin at unity gain	R_L = 10 kΩ,	C_L = 100 pF	25°C		52°			52°		
	Gain margin			25°C		10			10		dB

† Full range is −55°C to 125°C for M level part.

TLC2274-EP electrical characteristics at specified free-air temperature, V_{DD} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	TLC2274-EP			TLC2274A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	$V_{DD\pm}$ = ±2.5 V, V_O = 0 V,	V_{IC} = 0 V, R_S = 50 Ω	25°C		300	2500		300	950	μV
				Full range			3000			1500	
α_{VIO}	Temperature coefficient of input offset voltage			25°C to 125°C		2			2		μV/°C
	Input offset voltage long-term drift (see Note 5)			25°C		0.002			0.002		μV/mo
I_{IO}	Input offset current			25°C		0.5	60		0.5	60	pA
				Full range			800			800	
I_{IB}	Input bias current			25°C		1	60		1	60	pA
				Full range			800			800	
V_{ICR}	Common-mode input voltage	R_S = 50 Ω,	$\|V_{IO}\| \le$ 5 mV	25°C	0 to 4	−0.3 to 4.2		0 to 4	−0.3 to 4.2		V
				Full range	0 to 3.5			0 to 3.5			
V_{OH}	High-level output voltage	I_{OH} = −20 μA		25°C		4.99			4.99		V
		I_{OH} = −200 μA		25°C	4.85	4.93		4.85	4.93		
				Full range	4.85			4.85			
		I_{OH} = −1 mA		25°C	4.25	4.65		4.25	4.65		
				Full range	4.25			4.25			
V_{OL}	Low-level output voltage	V_{IC} = 2.5 V,	I_{OL} = 50 μA	25°C		0.01			0.01		V
		V_{IC} = 2.5 V, I_{OL} = 500 μA		25°C		0.09	0.15		0.09	0.15	
				Full range			0.15			0.15	
		V_{IC} = 2.5 V,	I_{OL} = 5 mA	25°C		0.9	1.5		0.9	1.5	
				Full range			1.5			1.5	
A_{VD}	Large-signal differential voltage amplification	V_{IC} = 2.5 V, V_O = 1 V to 4 V	R_L = 10 kΩ‡	25°C	10	35		10	35		V/mV
				Full range	10			10			
			R_L = 1 MΩ‡	25°C		175			175		
r_{id}	Differential input resistance			25°C		10^{12}			10^{12}		Ω
r_i	Common-mode input resistance			25°C		10^{12}			10^{12}		Ω
c_i	Common-mode input capacitance	f = 10 kHz,	N package	25°C		8			8		pF
z_o	Closed-loop output impedance	f = 1 MHz,	A_V = 10	25°C		140			140		Ω
CMRR	Common-mode rejection ratio	V_{IC} = 0 V to 2.7 V, V_O = 2.5 V,	R_S = 50 Ω	25°C	70	75		70	75		dB
				Full range	70			70			
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{DD}/\Delta V_{IO}$)	V_{DD} = 4.4 V to 16 V, V_{IC} = V_{DD}/2,	No load	25°C	80	95		80	95		dB
				Full range	80			80			
I_{DD}	Supply current	V_O = 2.5 V,	No load	25°C		4.4	6		4.4	6	mA
				Full range			6			6	

† Full range is −55°C to 125°C for M level part.
‡ Referenced to 2.5 V
NOTE 5: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.

TLC2274-EP operating characteristics at specified free-air temperature, V_{DD} = 5 V

PARAMETER		TEST CONDITIONS		T_A†	TLC2274-EP			TLC2274A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
SR	Slew rate at unity gain	V_O = 0.5 V to 2.5 V, R_L = 10 kΩ‡,	C_L = 100 pF‡	25°C	2.3	3.6		2.3	3.6		V/μs
				Full range	1.7			1.7			
V_n	Equivalent input noise voltage	f = 10 Hz		25°C		50			50		nV/√Hz
		f = 1 kHz		25°C		9			9		
$V_{N(PP)}$	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C		1			1		μV
		f = 0.1 Hz to 10 Hz		25°C		1.4			1.4		
I_n	Equivalent input noise current			25°C		0.6			0.6		fA/√Hz
THD + N	Total harmonic distortion plus noise	V_O = 0.5 V to 2.5 V, f = 20 kHz, R_L = 10 kΩ‡	A_V = 1	25°C		0.0013%			0.0013%		
			A_V = 10			0.004%			0.004%		
			A_V = 100			0.03%			0.03%		
	Gain-bandwidth product	f = 10 kHz, C_L = 100 pF‡	R_L = 10 kΩ‡,	25°C		2.18			2.18		MHz
B_{OM}	Maximum output-swing bandwidth	$V_{O(PP)}$ = 2 V, R_L = 10 kΩ‡,	A_V = 1, C_L = 100 pF‡	25°C		1			1		MHz
t_s	Settling time	A_V = −1, Step = 0.5 V to 2.5 V, R_L = 10 kΩ‡, C_L = 100 pF‡	To 0.1%	25°C		1.5			1.5		μs
			To 0.01%			2.6			2.6		
ϕ_m	Phase margin at unity gain	R_L = 10 kΩ‡,	C_L = 100 pF‡	25°C		50°			50°		
	Gain margin			25°C		10			10		dB

† Full range is −55°C to 125°C for M level part.
‡ Referenced to 2.5 V

TLC2274-EP electrical characteristics at specified free-air temperature, $V_{DD\pm}$ = ±5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	TLC2274-EP			TLC2274A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{IC} = 0 V, V_O = 0 V, R_S = 50 Ω		25°C		300	2500		300	950	µV
				Full range			3000			1500	
α_{VIO}	Temperature coefficient of input offset voltage			25°C to 125°C		2			2		µV/°C
	Input offset voltage long-term drift (see Note 5)			25°C		0.002			0.002		µV/mo
I_{IO}	Input offset current			25°C		0.5	60		0.5	60	pA
				Full range			800			800	
I_{IB}	Input bias current			25°C		1	60		1	60	pA
				Full range			800			800	
V_{ICR}	Common-mode input voltage	R_S = 50 Ω, $\|V_{IO}\| \le$ 5 mV		25°C	−5 to 4	−5.3 to 4.2		−5 to 4	−5.3 to 4.2		V
				Full range	−5 to 3.5			−5 to 3.5			
V_{OM+}	Maximum positive peak output voltage	I_O = −20 µA		25°C		4.99			4.99		V
		I_O = −200 µA		25°C	4.85	4.93		4.85	4.93		
				Full range	4.85			4.85			
		I_O = −1 mA		25°C	4.25	4.65		4.25	4.65		
				Full range	4.25			4.25			
V_{OM-}	Maximum negative peak output voltage	V_{IC} = 0 V, I_O = 50 µA		25°C		−4.99			−4.99		V
		V_{IC} = 0 V, I_O = 500 µA		25°C	−4.85	−4.91		−4.85	−4.91		
				Full range	−4.85			−4.85			
		V_{IC} = 0 V, I_O = 5 mA		25°C	−3.5	−4.1		−3.5	−4.1		
				Full range	−3.5			−3.5			
A_{VD}	Large-signal differential voltage amplification	V_O = ±4 V	R_L = 10 kΩ	25°C	20	50		20	50		V/mV
				Full range	20			20			
			R_L = 1 MΩ	25°C		300			300		
r_{id}	Differential input resistance			25°C		10^{12}			10^{12}		Ω
r_i	Common-mode input resistance			25°C		10^{12}			10^{12}		Ω
c_i	Common-mode input capacitance	f = 10 kHz, N package		25°C		8			8		pF
z_o	Closed-loop output impedance	f = 1 MHz, A_V = 10		25°C		130			130		Ω
CMRR	Common-mode rejection ratio	V_{IC} = −5 V to 2.7 V, V_O = 0 V, R_S = 50 Ω		25°C	75	80		75	80		dB
				Full range	75			75			
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{DD\pm}/\Delta V_{IO}$)	$V_{DD\pm}$ = ± 2.2 V to ±8 V, V_{IC} = 0 V, No load		25°C	80	95		80	95		dB
				Full range	80			80			
I_{DD}	Supply current	V_O = 0 V, No load		25°C		4.8	6		4.8	6	mA
				Full range			6			6	

† Full range is −55°C to 125°C for M level part.

NOTE 5: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.

TLC2274-EP operating characteristics at specified free-air temperature, $V_{DD\pm}$ = ±5 V

PARAMETER		TEST CONDITIONS		T_A†	TLC2274-EP			TLC2274A-EP			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
SR	Slew rate at unity gain	V_O = ±2.3 V, C_L = 100 pF	R_L = 10 kΩ,	25°C	2.3	3.6		2.3	3.6		V/μs
				Full range	1.7			1.7			
V_n	Equivalent input noise voltage	f = 10 Hz		25°C		50			50		nV/√Hz
		f = 1 kHz		25°C		9			9		
$V_{N(PP)}$	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 1 Hz		25°C		1			1		μV
		f = 0.1 Hz to 10 Hz		25°C		1.4			1.4		
I_n	Equivalent input noise current			25°C		0.6			0.6		fA/√Hz
THD + N	Total harmonic distortion plus noise	V_O = ±2.3 V, R_L = 10 kΩ, f = 20 kHz	A_V = 1	25°C		0.0011%			0.0011%		
			A_V = 10			0.004%			0.004%		
			A_V = 100			0.03%			0.03%		
	Gain-bandwidth product	f = 10 kHz, C_L = 100 pF	R_L = 10 kΩ,	25°C		2.25			2.25		MHz
B_{OM}	Maximum output-swing bandwidth	$V_{O(PP)}$ = 4.6 V, R_L = 10 kΩ,	A_V = 1, C_L = 100 pF	25°C		0.54			0.54		MHz
t_s	Settling time	A_V = −1, Step = −2.3 V to 2.3 V, R_L = 10 kΩ, C_L = 100 pF	To 0.1%	25°C		1.5			1.5		μs
			To 0.01%			3.2			3.2		
ϕ_m	Phase margin at unit gain	R_L = 10 kΩ,	C_L = 100 pF	25°C		52°			52°		
	Gain margin			25°C		10			10		dB

† Full range is −55°C to 125°C for M level part.

TYPICAL CHARACTERISTICS

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NOTE: For all graphs where V_{DD} = 5 V, all loads are referenced to 2.5 V.

TYPICAL CHARACTERISTICS

DISTRIBUTION OF TLC2272
INPUT OFFSET VOLTAGE

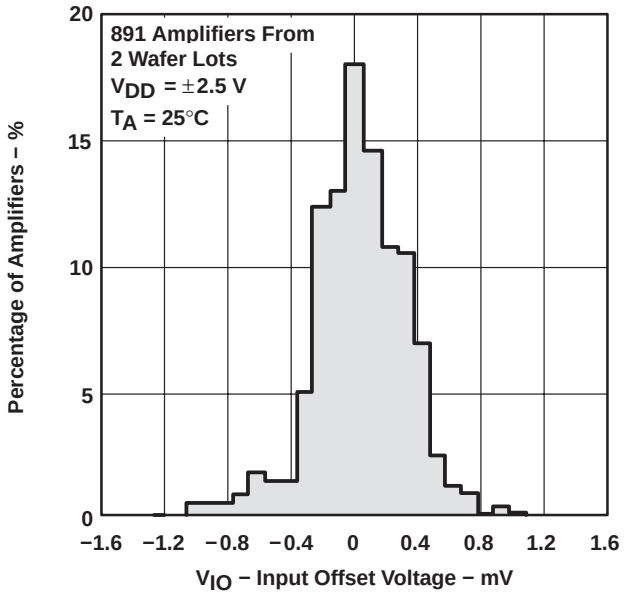


Figure 1

DISTRIBUTION OF TLC2272
INPUT OFFSET VOLTAGE

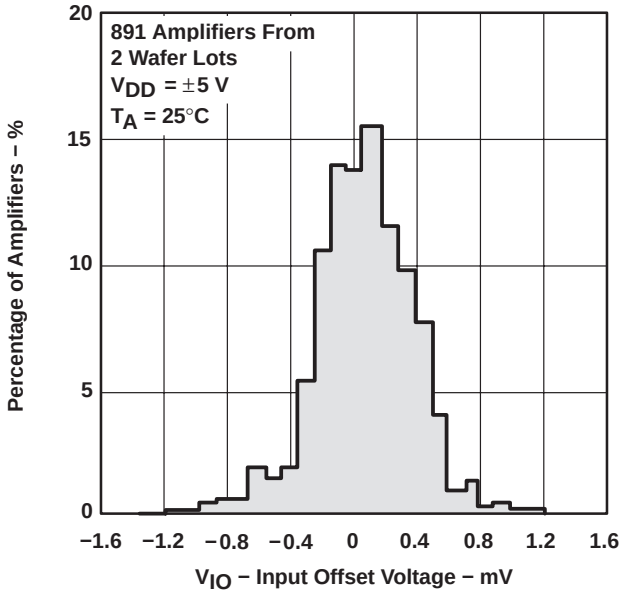


Figure 2

DISTRIBUTION OF TLC2274
INPUT OFFSET VOLTAGE

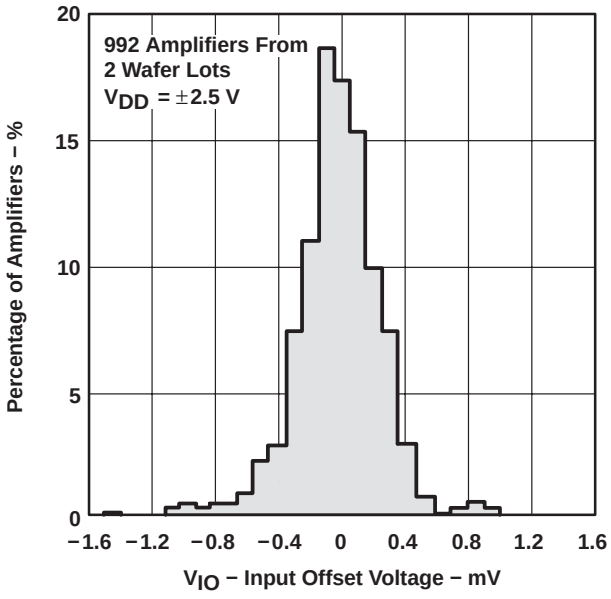


Figure 3

DISTRIBUTION OF TLC2274
INPUT OFFSET VOLTAGE

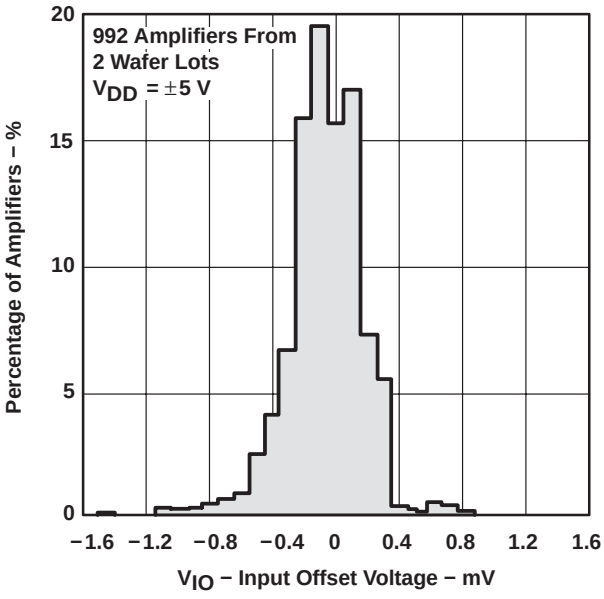


Figure 4

TYPICAL CHARACTERISTICS

INPUT OFFSET VOLTAGE vs COMMON-MODE VOLTAGE

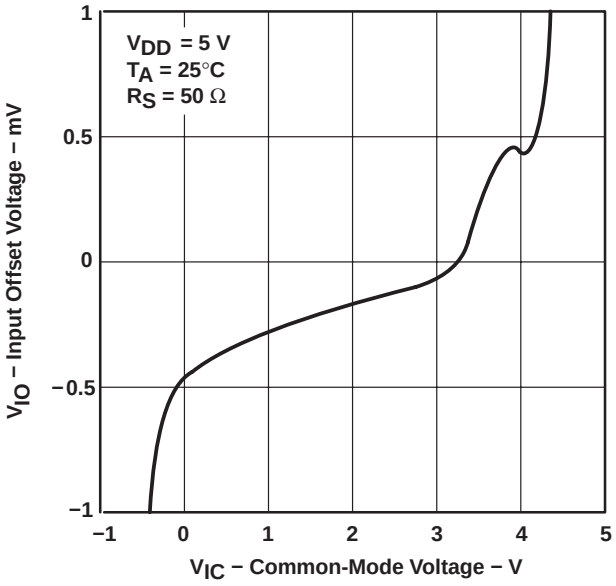


Figure 5

INPUT OFFSET VOLTAGE vs COMMON-MODE VOLTAGE

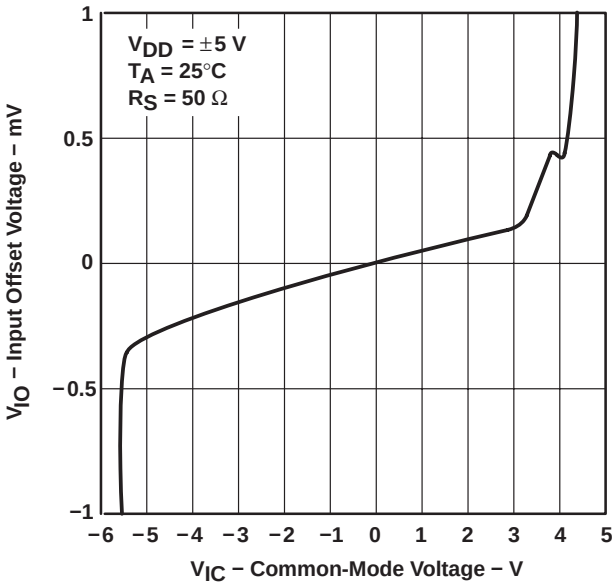


Figure 6

DISTRIBUTION OF TLC2272 vs INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT†

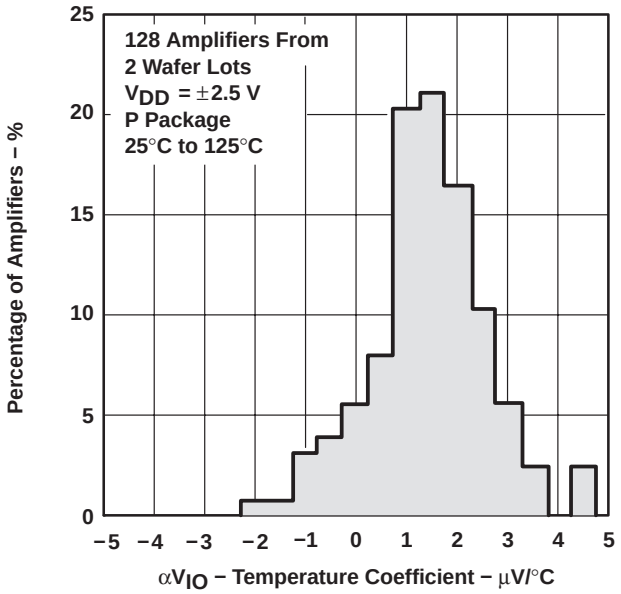


Figure 7

DISTRIBUTION OF TLC2272 vs INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT†

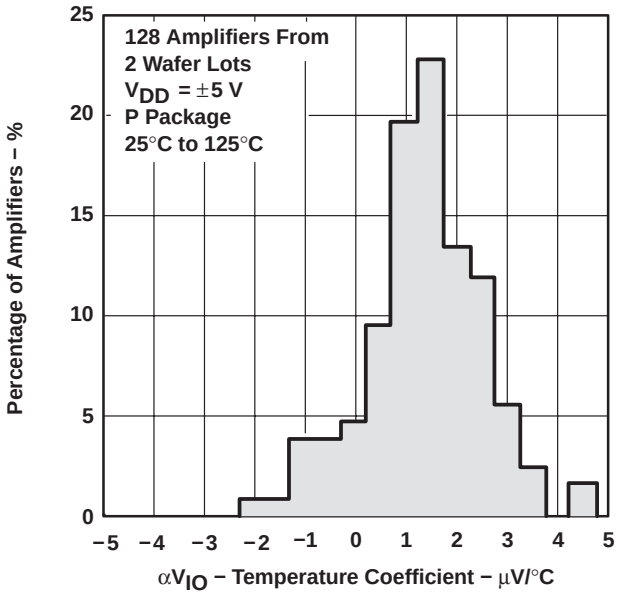


Figure 8

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

DISTRIBUTION OF TLC2274 vs INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT†

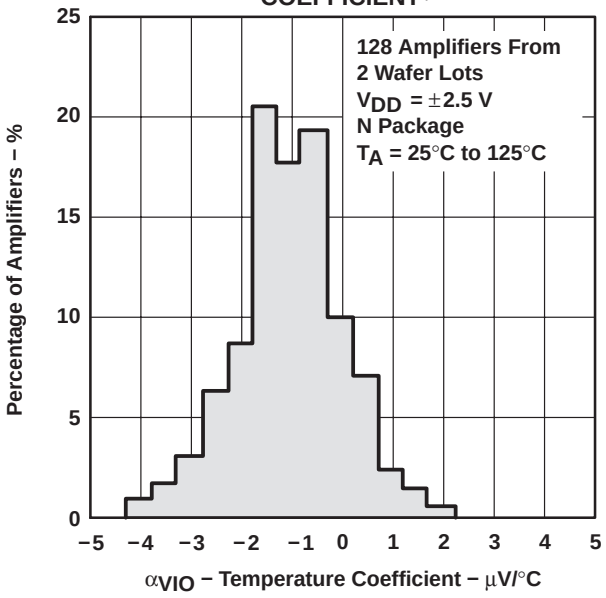


Figure 9

DISTRIBUTION OF TLC2274 vs INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT†

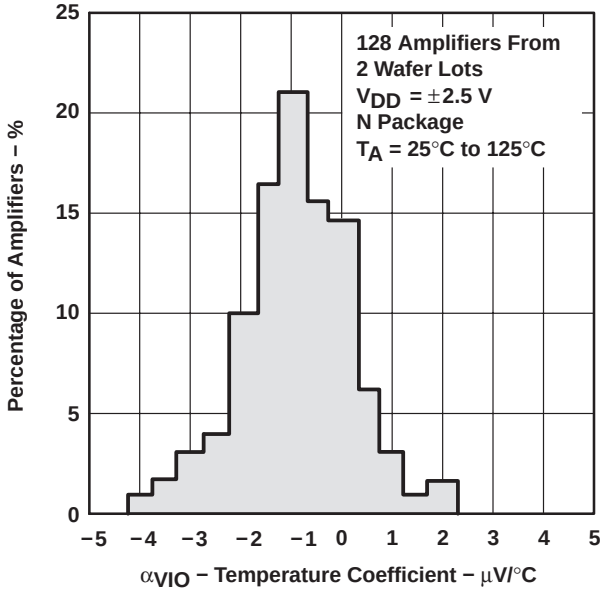


Figure 10

INPUT BIAS AND INPUT OFFSET CURRENT† vs FREE-AIR TEMPERATURE

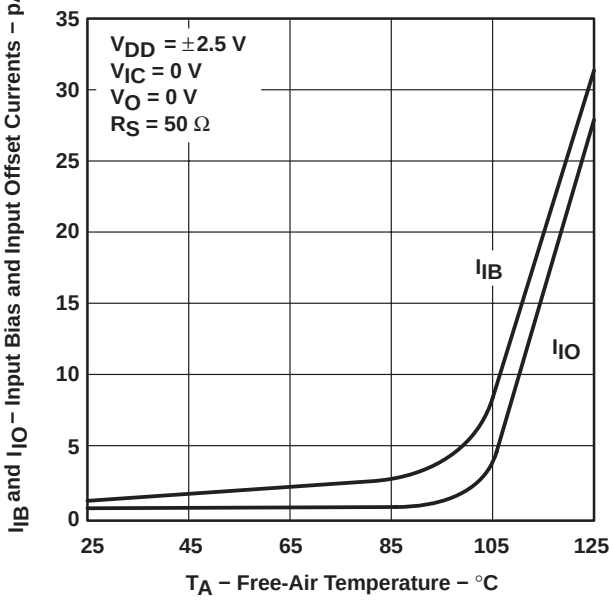


Figure 11

INPUT VOLTAGE vs SUPPLY VOLTAGE

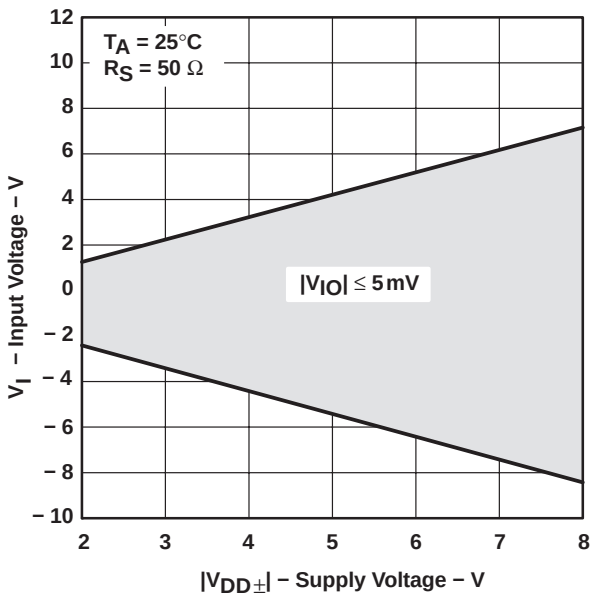


Figure 12

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

INPUT VOLTAGE† vs FREE-AIR TEMPERATURE

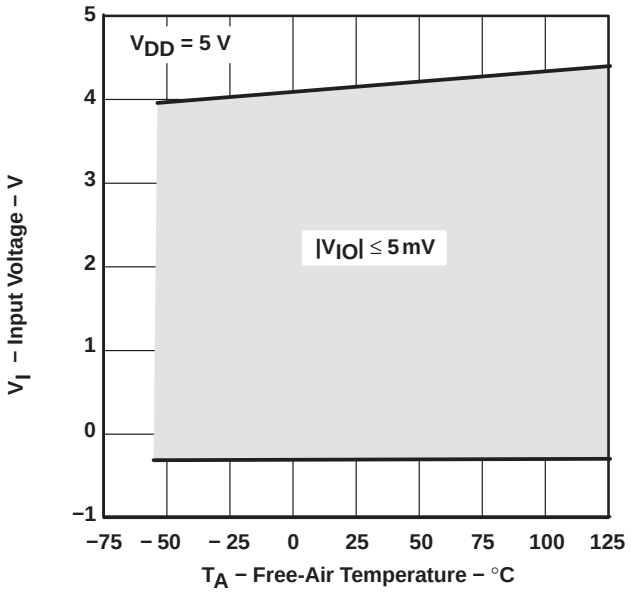


Figure 13

HIGH-LEVEL OUTPUT VOLTAGE† vs HIGH-LEVEL OUTPUT CURRENT

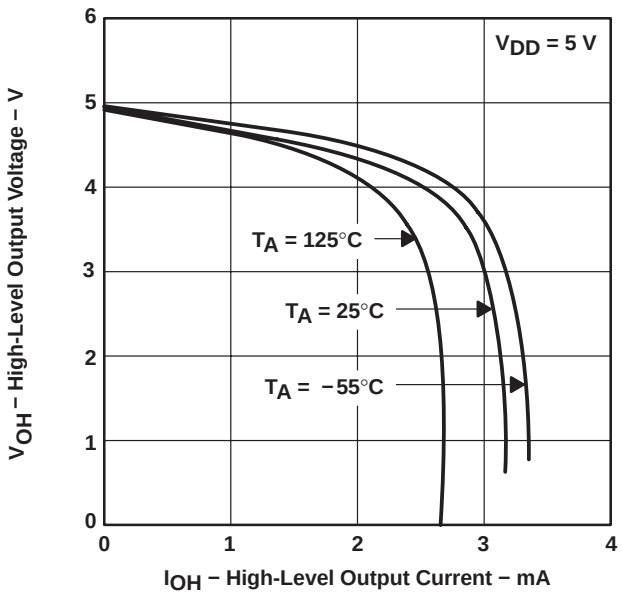


Figure 14

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

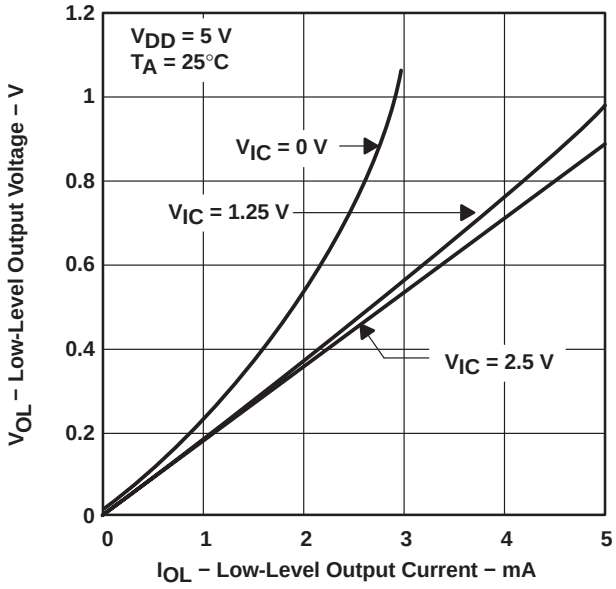


Figure 15

LOW-LEVEL OUTPUT VOLTAGE† vs LOW-LEVEL OUTPUT CURRENT

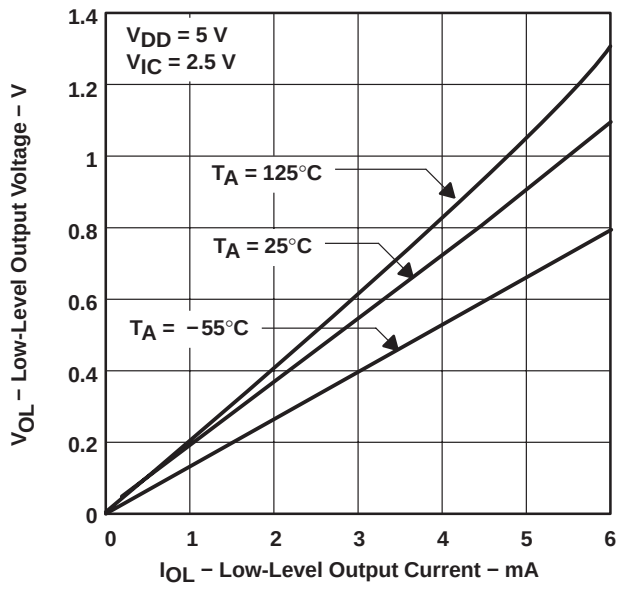


Figure 16

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

MAXIMUM POSITIVE PEAK OUTPUT VOLTAGE† vs OUTPUT CURRENT

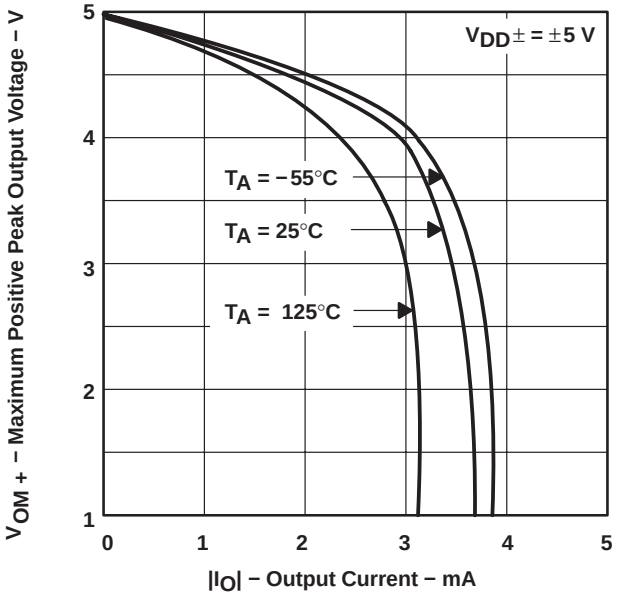


Figure 17

MAXIMUM NEGATIVE PEAK OUTPUT VOLTAGE† vs OUTPUT CURRENT

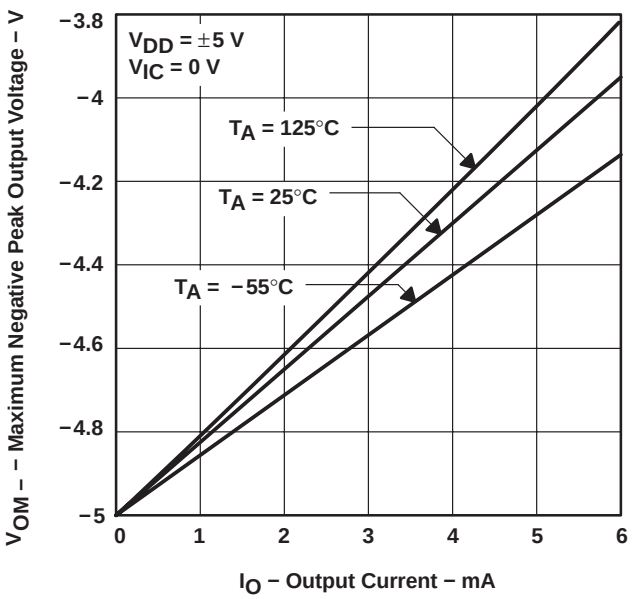


Figure 18

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs FREQUENCY

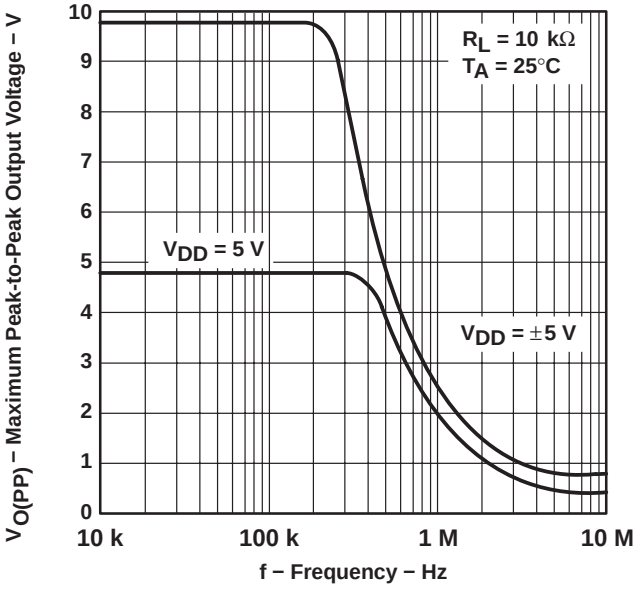


Figure 19

SHORT-CIRCUIT OUTPUT CURRENT vs SUPPLY VOLTAGE

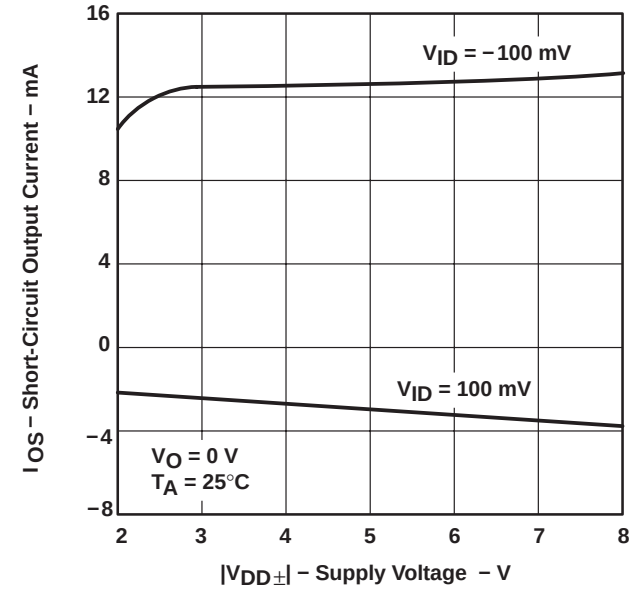


Figure 20

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

SHORT-CIRCUIT OUTPUT CURRENT† vs FREE-AIR TEMPERATURE

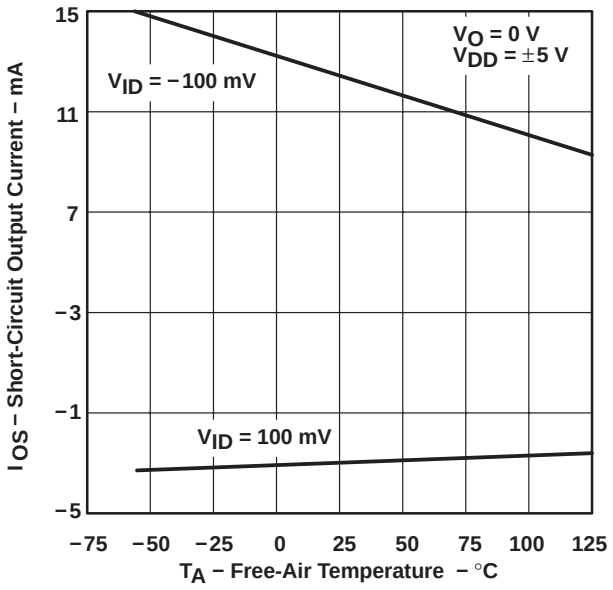


Figure 21

OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

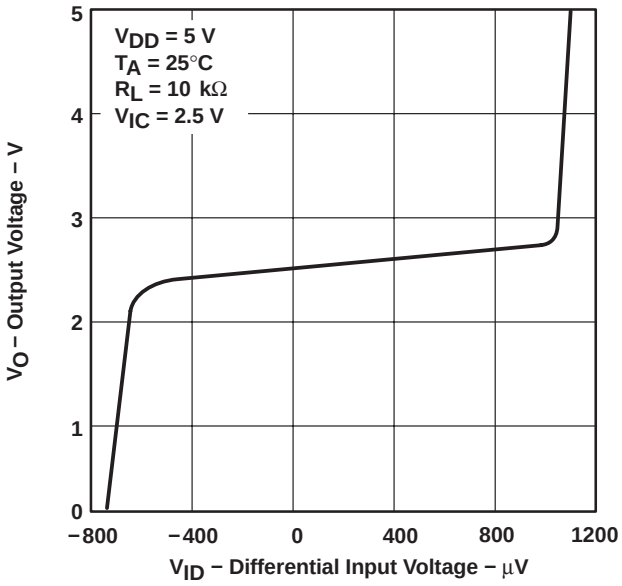


Figure 22

OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

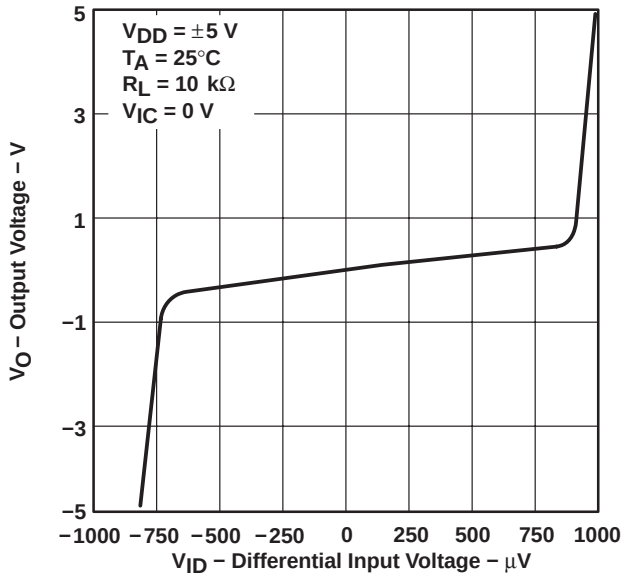


Figure 23

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs LOAD RESISTANCE

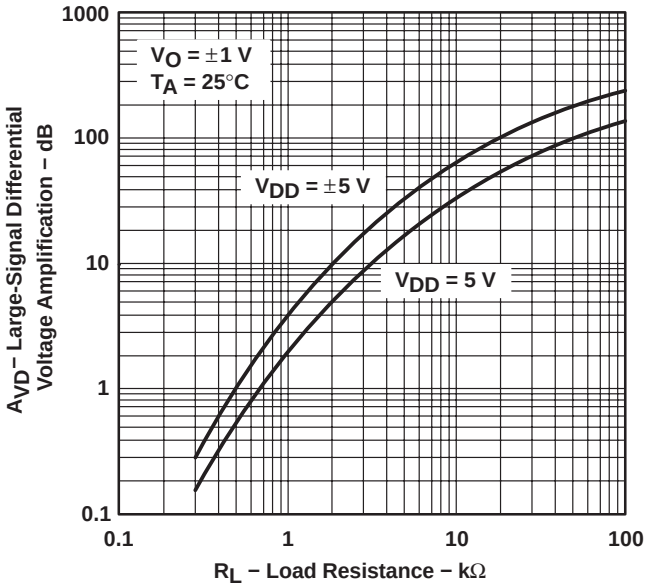


Figure 24

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE MARGIN vs FREQUENCY

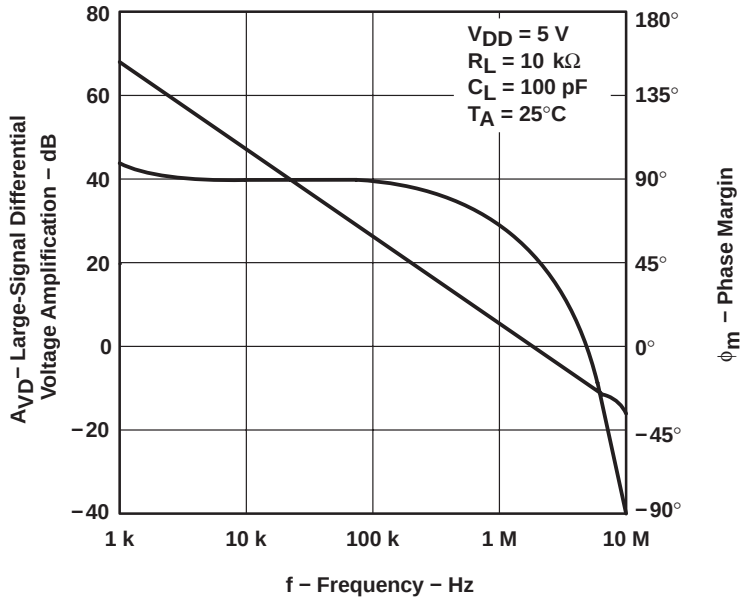


Figure 25

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE MARGIN vs FREQUENCY

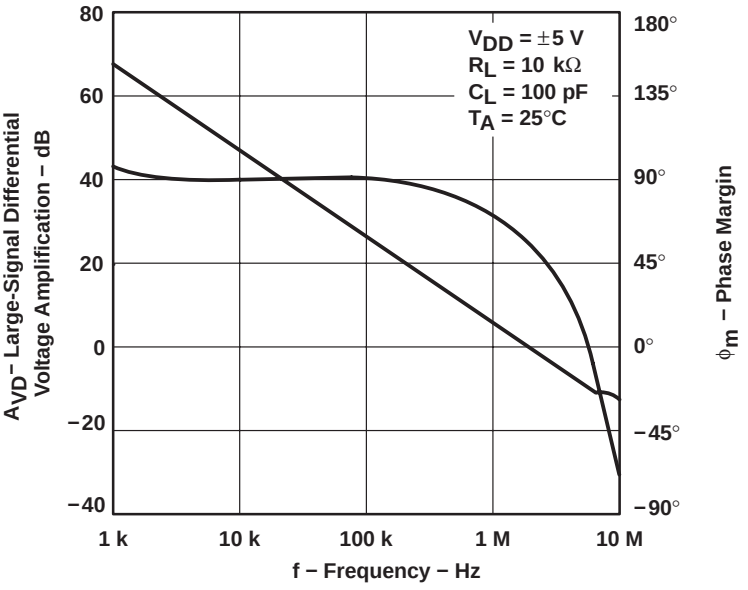


Figure 26

TYPICAL CHARACTERISTICS

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION† vs FREE-AIR TEMPERATURE

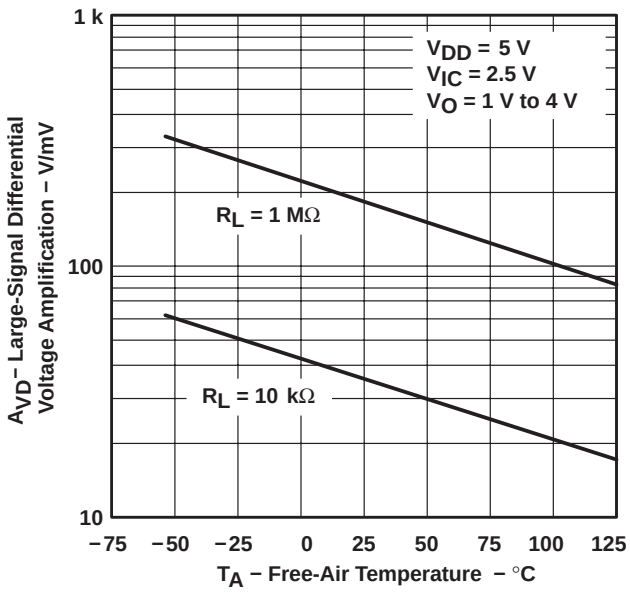


Figure 27

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION† vs FREE-AIR TEMPERATURE

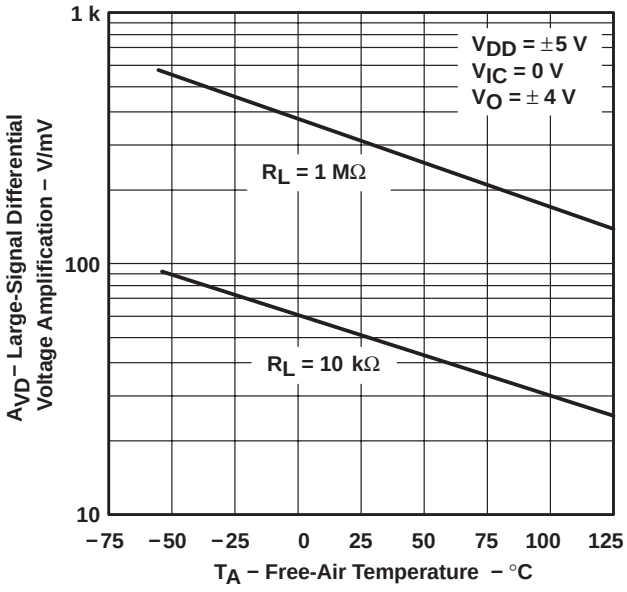


Figure 28

OUTPUT IMPEDANCE vs FREQUENCY

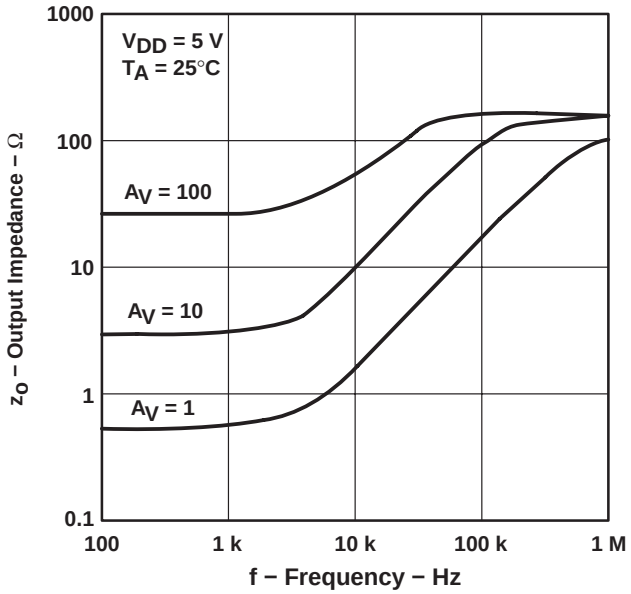


Figure 29

OUTPUT IMPEDANCE vs FREQUENCY

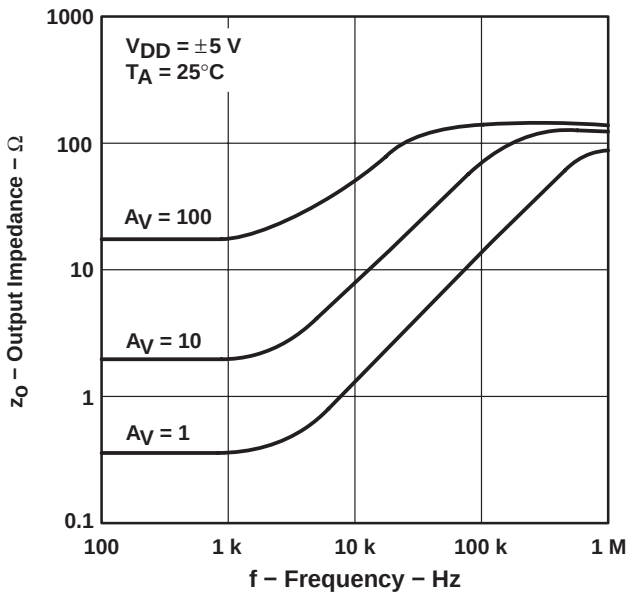


Figure 30

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

COMMON-MODE REJECTION RATIO
vs
FREQUENCY

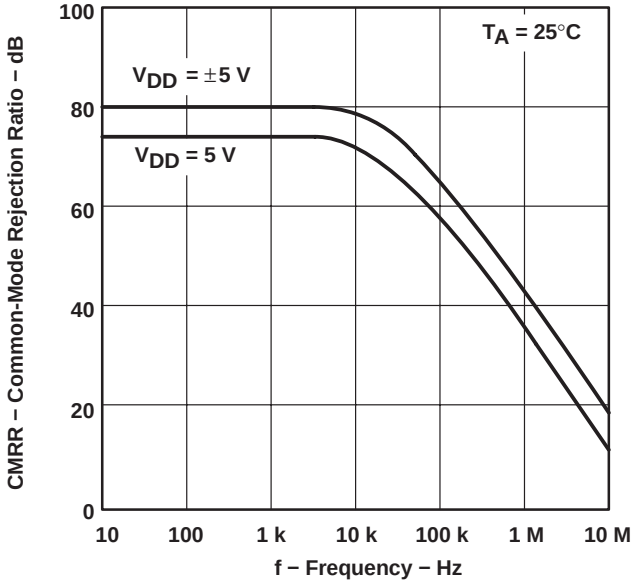


Figure 31

COMMON-MODE REJECTION RATIO
vs
FREE-AIR TEMPERATURE

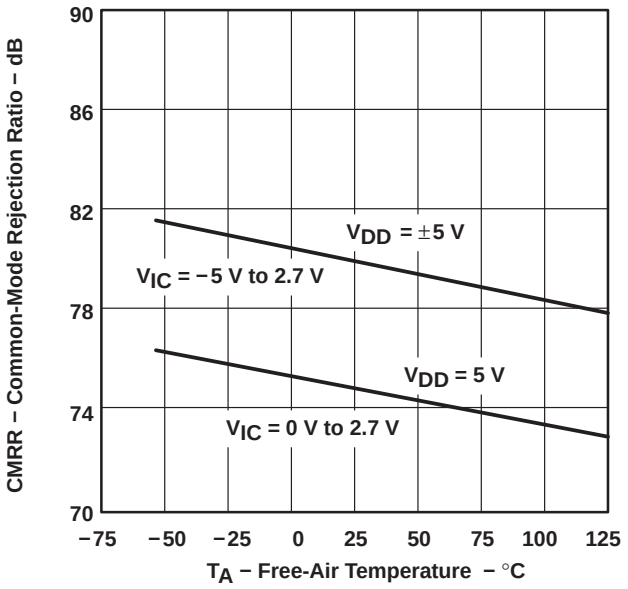


Figure 32

SUPPLY-VOLTAGE REJECTION RATIO
vs
FREQUENCY

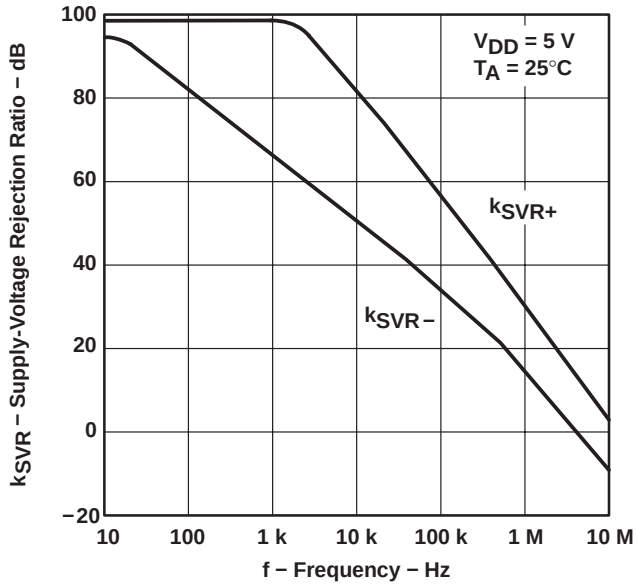


Figure 33

SUPPLY-VOLTAGE REJECTION RATIO
vs
FREQUENCY

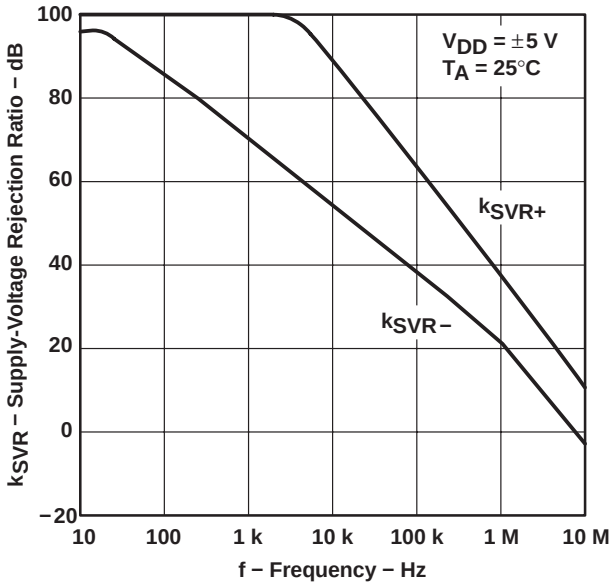


Figure 34

TYPICAL CHARACTERISTICS

SUPPLY VOLTAGE REJECTION RATIO† vs FREE-AIR TEMPERATURE

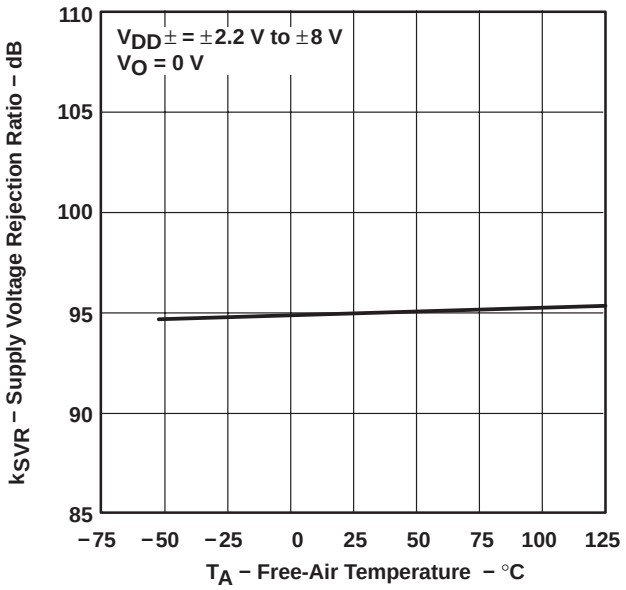


Figure 35

TLC2272 SUPPLY CURRENT† vs SUPPLY VOLTAGE

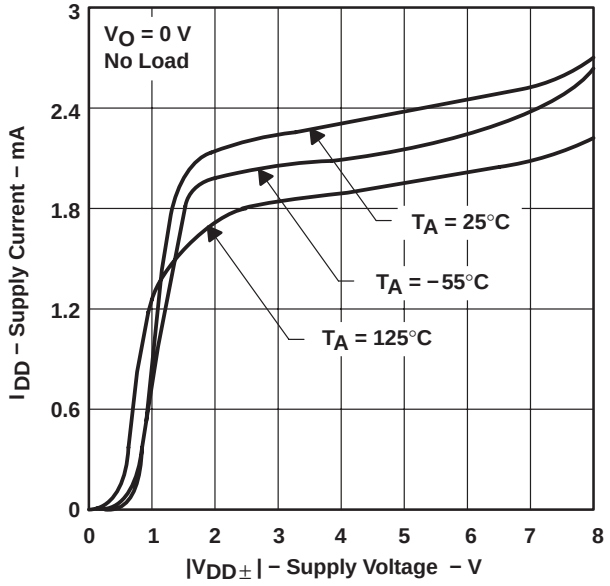


Figure 36

TLC2274 SUPPLY CURRENT† vs SUPPLY VOLTAGE

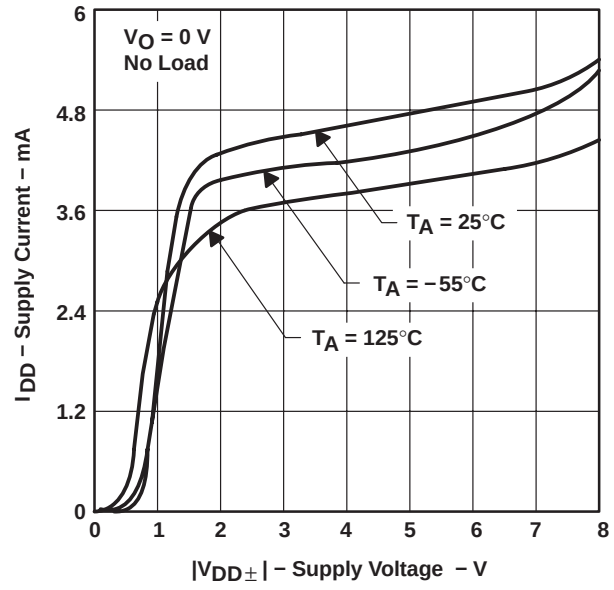


Figure 37

TLC2272 SUPPLY CURRENT† vs FREE-AIR TEMPERATURE

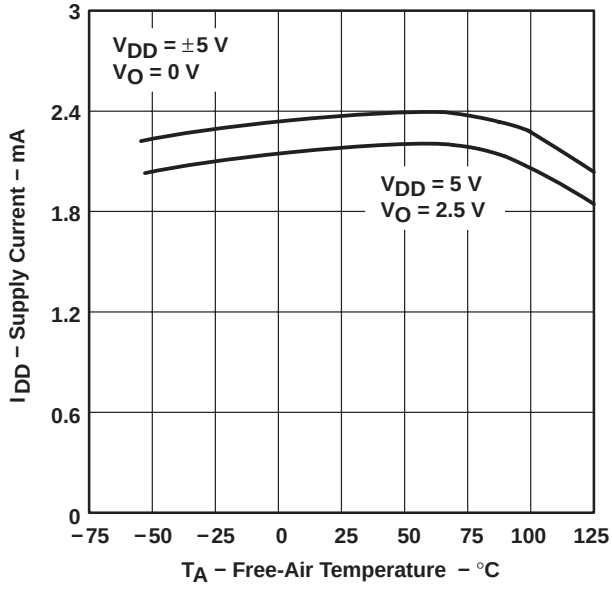


Figure 38

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

TLC2274
SUPPLY CURRENT†
vs
FREE-AIR TEMPERATURE

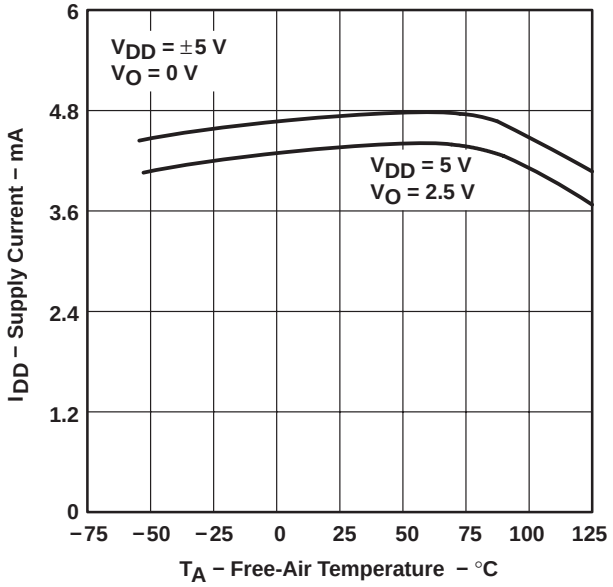


Figure 39

SLEW RATE
vs
LOAD CAPACITANCE

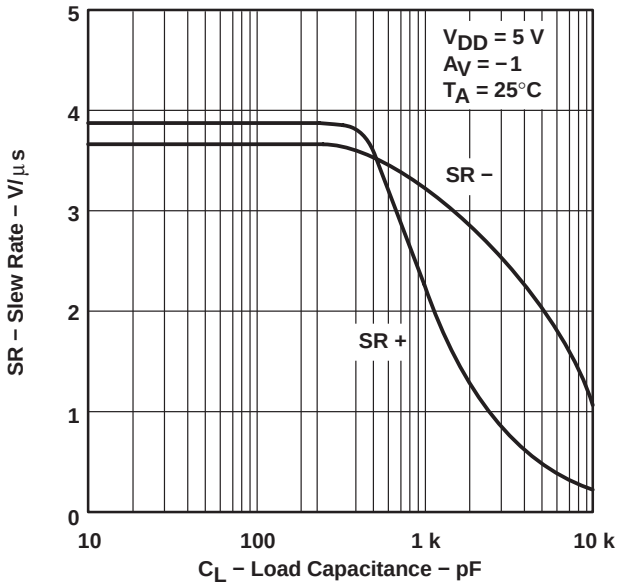


Figure 40

SLEW RATE†
vs
FREE-AIR TEMPERATURE

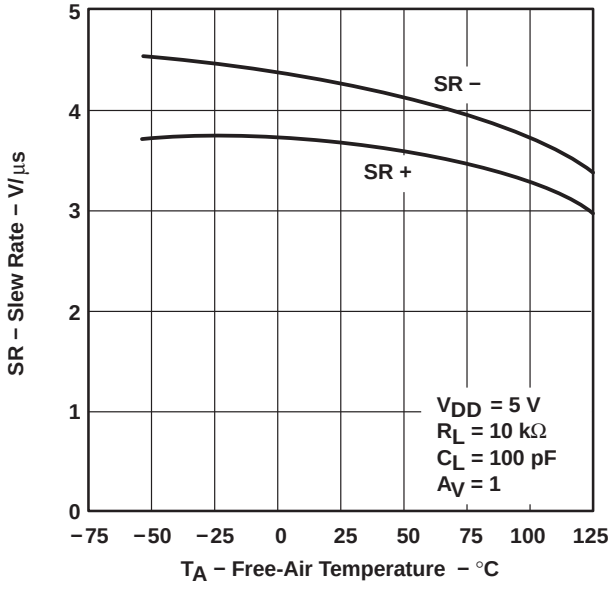


Figure 41

INVERTING LARGE-SIGNAL PULSE RESPONSE

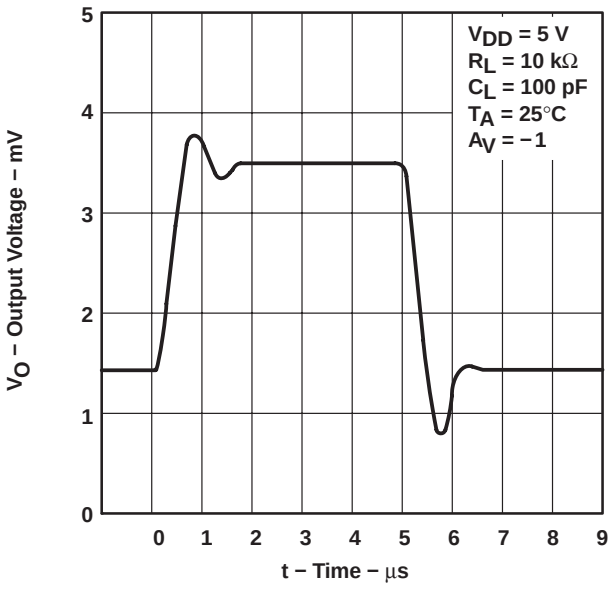


Figure 42

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

INVERTING LARGE-SIGNAL PULSE RESPONSE

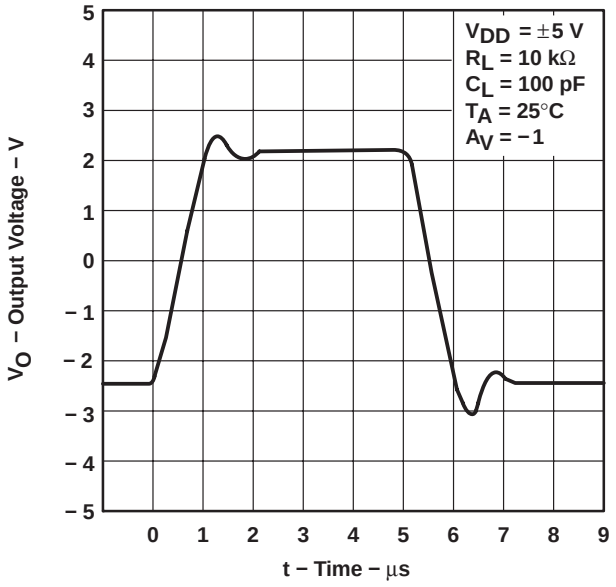


Figure 43

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE

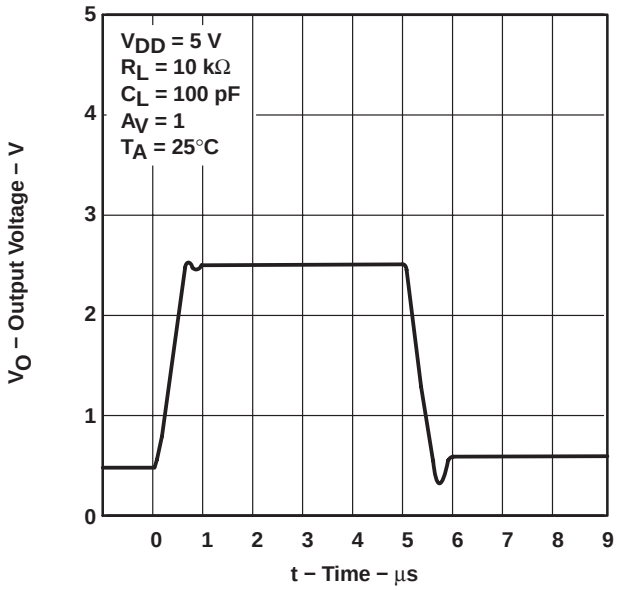


Figure 44

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE

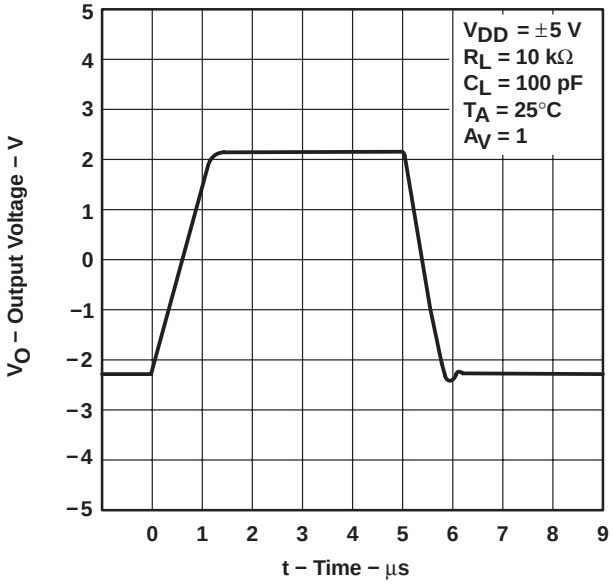


Figure 45

INVERTING SMALL-SIGNAL PULSE RESPONSE

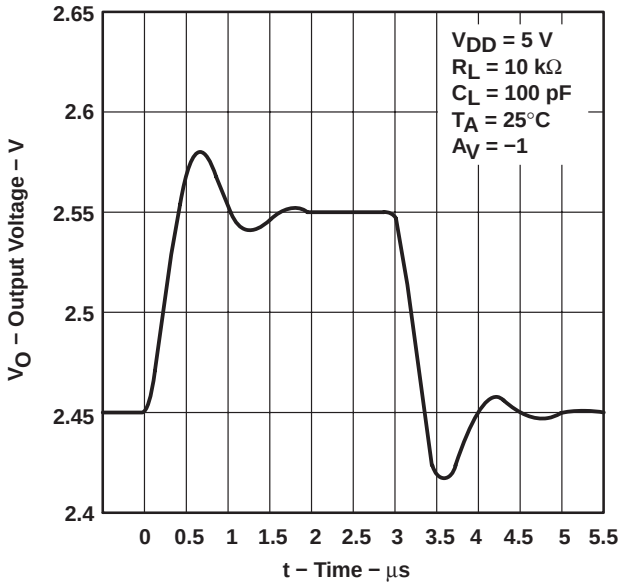


Figure 46

TYPICAL CHARACTERISTICS

INVERTING SMALL-SIGNAL PULSE RESPONSE

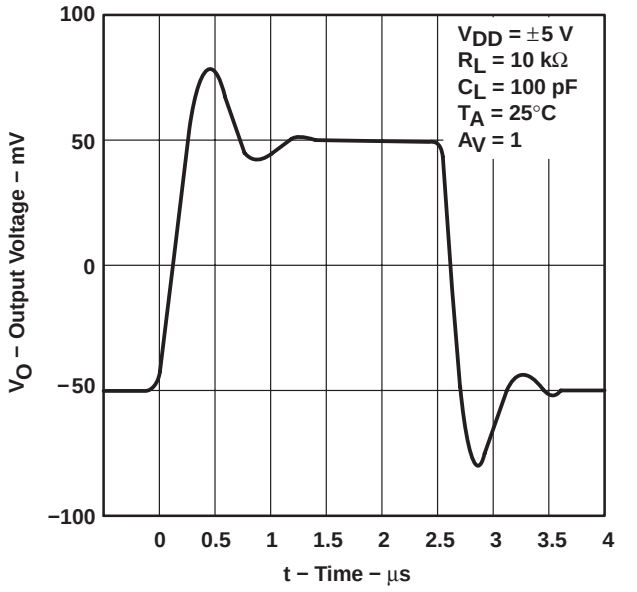


Figure 47

VOLTAGE-FOLLOWER
SMALL-SIGNAL PULSE RESPONSE

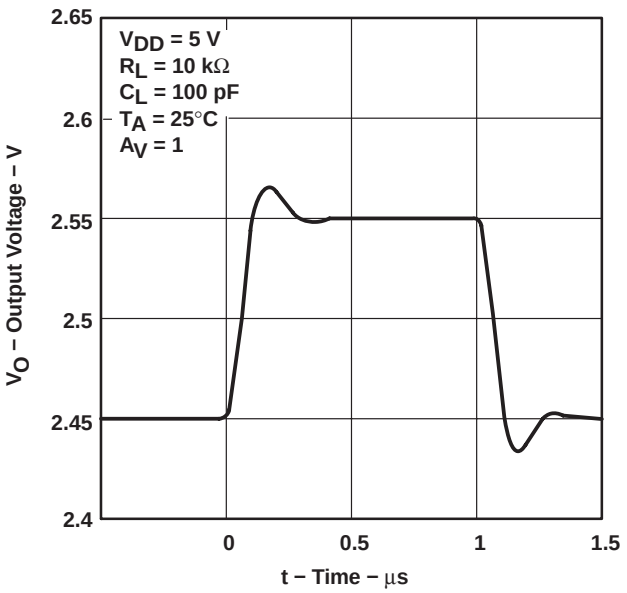


Figure 48

VOLTAGE-FOLLOWER
SMALL-SIGNAL PULSE RESPONSE

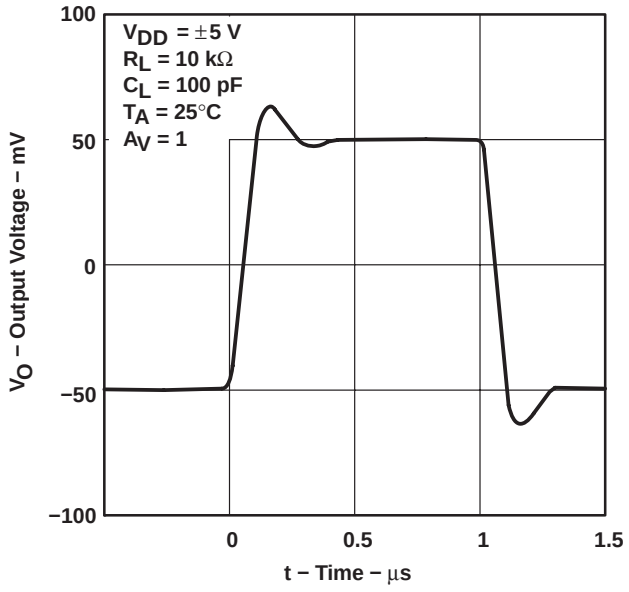


Figure 49

EQUIVALENT INPUT NOISE VOLTAGE
vs
FREQUENCY

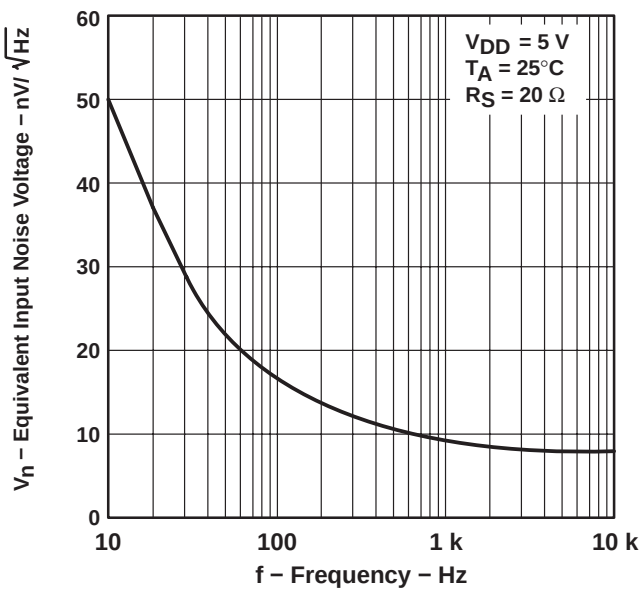


Figure 50

TYPICAL CHARACTERISTICS

EQUIVALENT INPUT NOISE VOLTAGE vs FREQUENCY

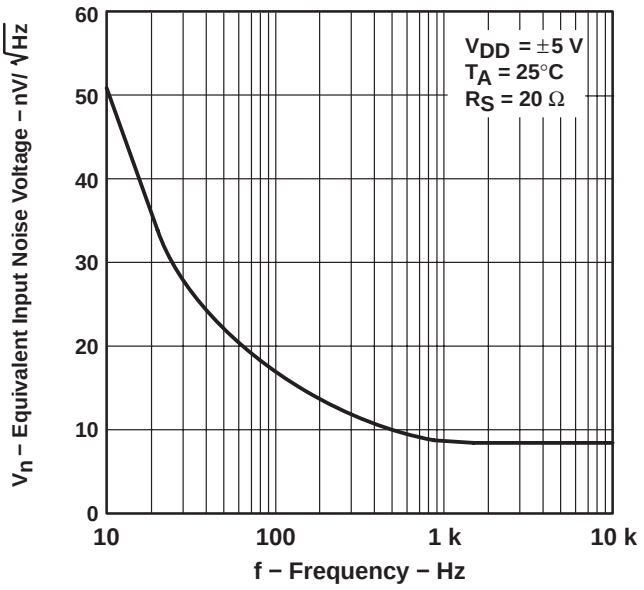


Figure 51

NOISE VOLTAGE OVER A 10 SECOND PERIOD

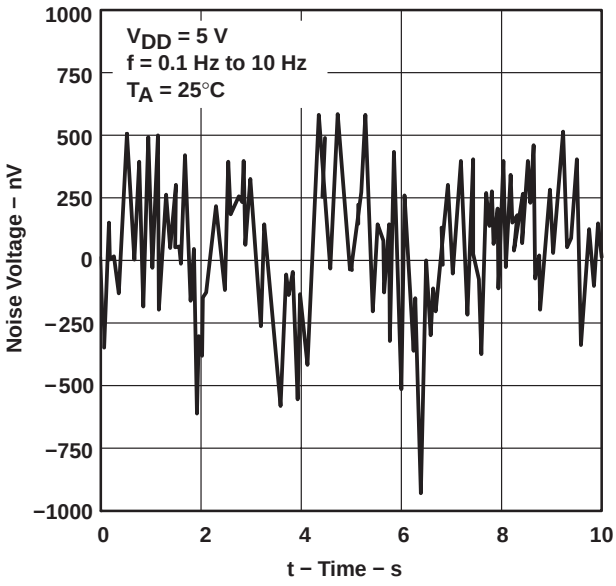


Figure 52

INTEGRATED NOISE VOLTAGE vs FREQUENCY

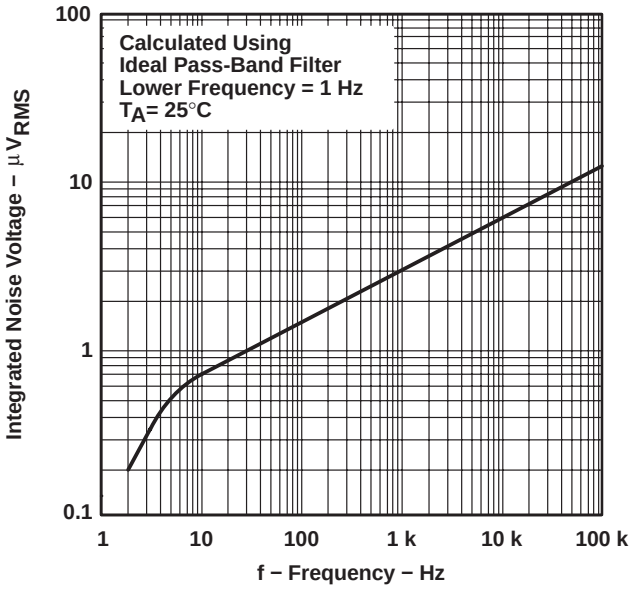


Figure 53

TOTAL HARMONIC DISTORTION PLUS NOISE vs FREQUENCY

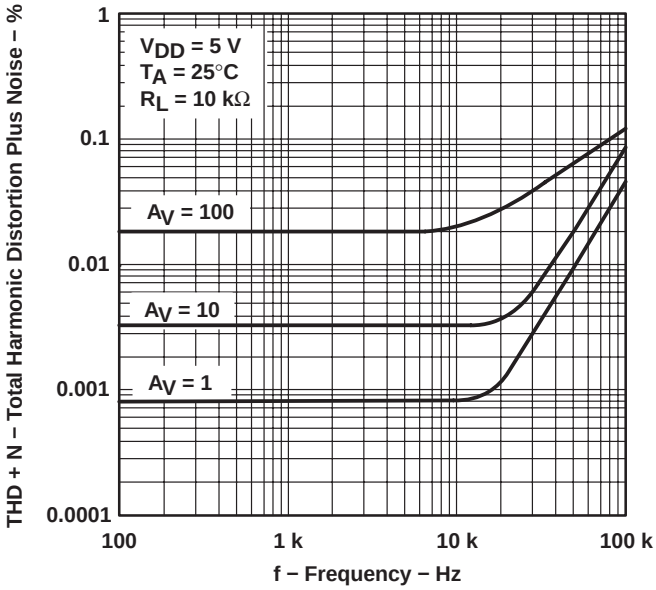


Figure 54

TYPICAL CHARACTERISTICS

GAIN-BANDWIDTH PRODUCT vs SUPPLY VOLTAGE

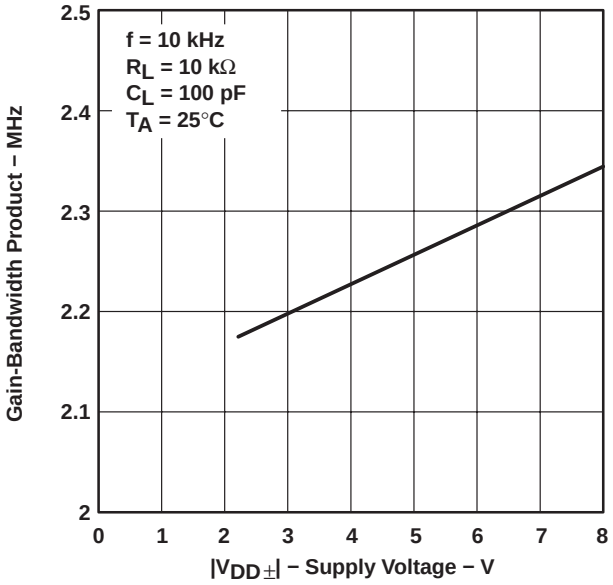


Figure 55

GAIN-BANDWIDTH PRODUCT† vs FREE-AIR TEMPERATURE

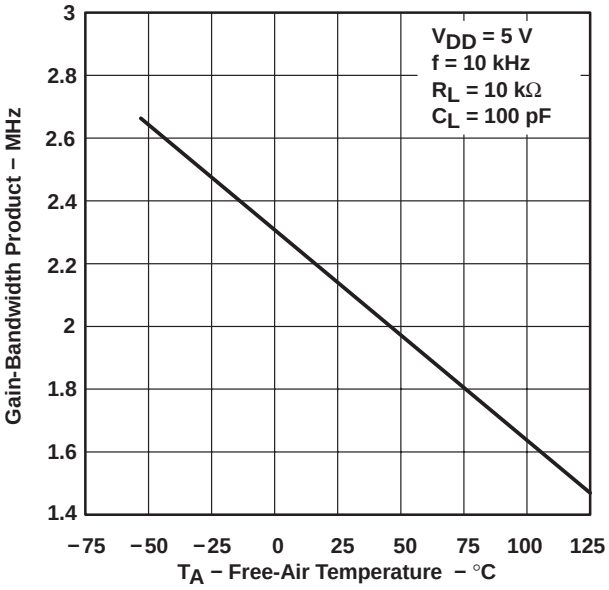


Figure 56

PHASE MARGIN vs LOAD CAPACITANCE

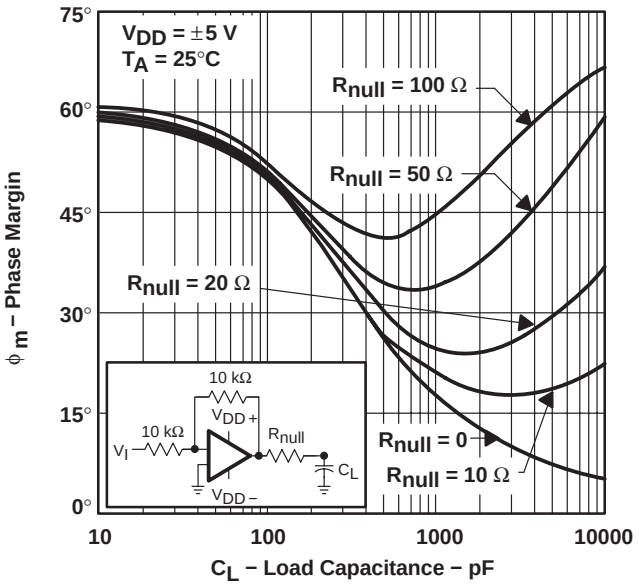


Figure 57

GAIN MARGIN vs LOAD CAPACITANCE

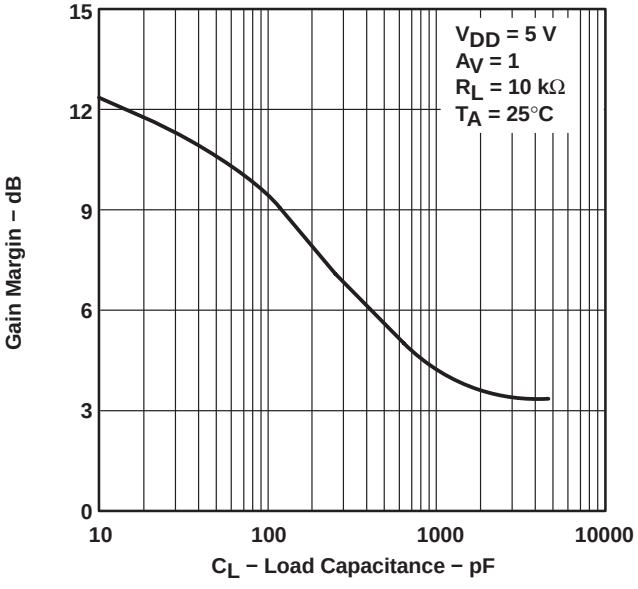


Figure 58

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

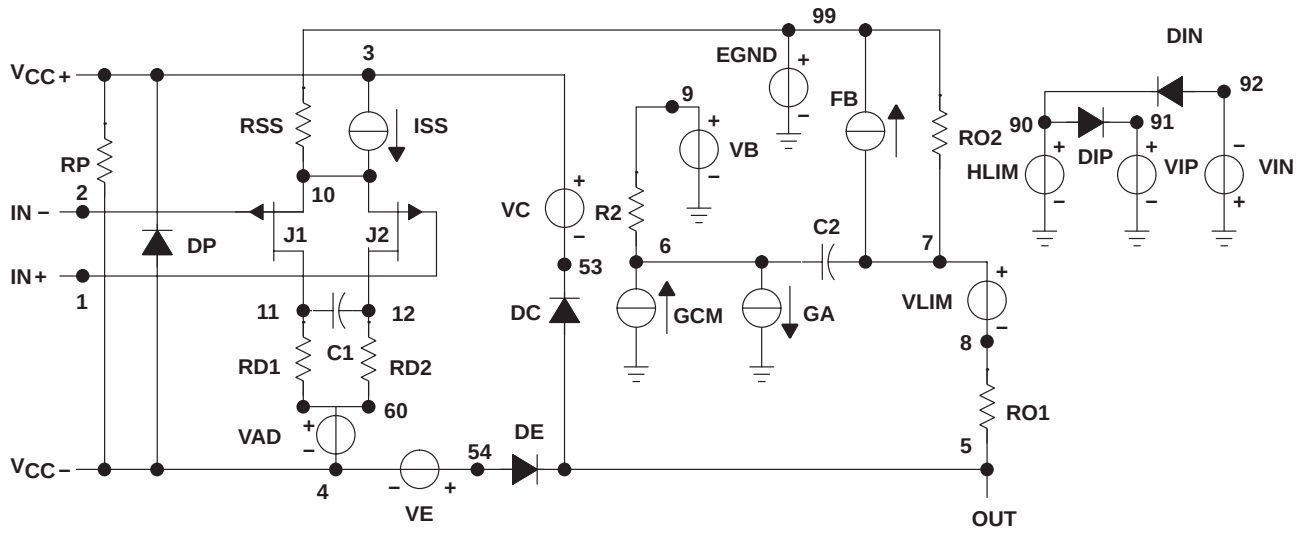
APPLICATION INFORMATION

macromodel information

Macromodel information provided was derived using Microsim *Parts*™, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 6) and subcircuit in Figure 59 were generated using the TLC227x typical electrical and operating characteristics at T_A = 25°C. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 6: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, “Macromodeling of Integrated Circuit Operational Amplifiers”, *IEEE Journal of Solid-State Circuits,* SC-9, 353 (1974).




```
.SUBCKT TLC227x 1 2 3 4 5
C1      11      12      1214E−12
C2      6       7       760.00E−12
DC      5       53      DX
DE      54      5       DX
DLP     90      91      DX
DLN     92      90      DX
DP      4       3       DX
EGND    99      0       POLY (2) (3,0) (4,) 0 .5 .5
FB      99      0       POLY (5) VB VC VE VLP VLN 0
+ 984.9E3 −1E6 1E6 1E6 −1E6
GA      6       0       11 12 377.0E−6
GCM 0 6 10 99 134E−9
ISS     3       10      DC 216.OE−6
HLIM    90      0       VLIM 1K
J1      11      2       10 JX
J2      12      1       10 JX
R2      6       9       100.OE3
RD1     60      11      12.653E3
RD2     60      12      122.653E3
R01     8       5       50
R02     7       99      50
RP      3       2       4.310E3
RSS     10      99      25.9E3
VAD     60      4       −.5
VB      9       0       DC 0
VC 3 53 DC .78
VE      54      4       DC .78
VLIM    7       8       DC 0
VLP     91      0       DC 1.9
VLN     0       92      DC 9.4
.MODEL DX D (IS=800.0E−18)
.MODEL JX PJF (IS=1.500E−12BETA=1.316E-3
+ VTO=−.270)
.ENDS
```

Figure 59. Boyle Macromodel and Subcircuit

PSpice and *Parts* are trademarks of MicroSim Corporation.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
TLC2272AMDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC2272AMDREPG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC2274AMDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC2274AMPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC2274MDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC2274MPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03618-01XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03618-02UE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03618-02YE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03618-04UE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03618-04YE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TLC2272A-EP, TLC2274-EP, TLC2274A-EP :

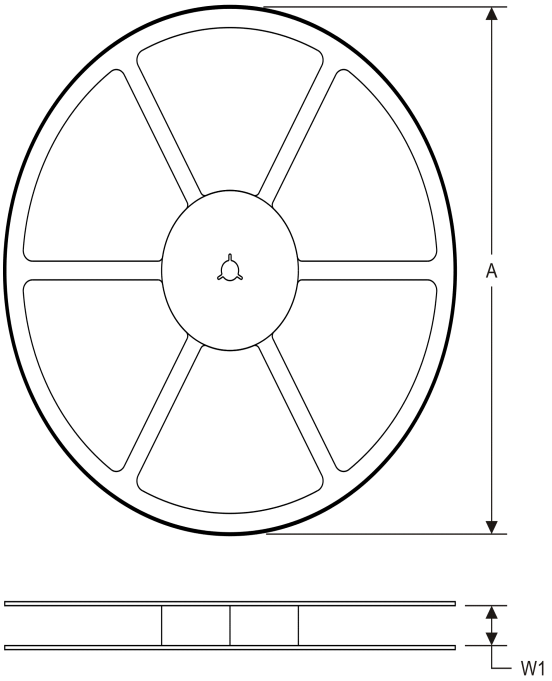
- Catalog: TLC2272A, TLC2274, TLC2274A
- Automotive: TLC2272A-Q1, TLC2274-Q1, TLC2274A-Q1
- Military: TLC2272AM, TLC2274M, TLC2274AM

NOTE: Qualified Version Definitions:

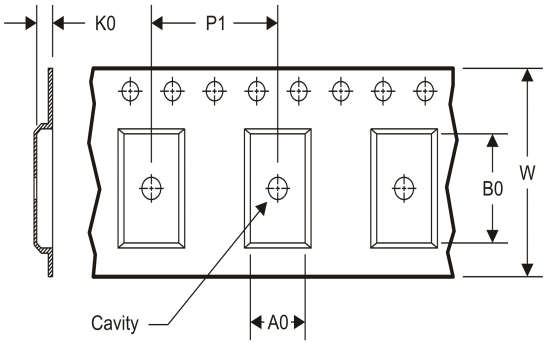
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



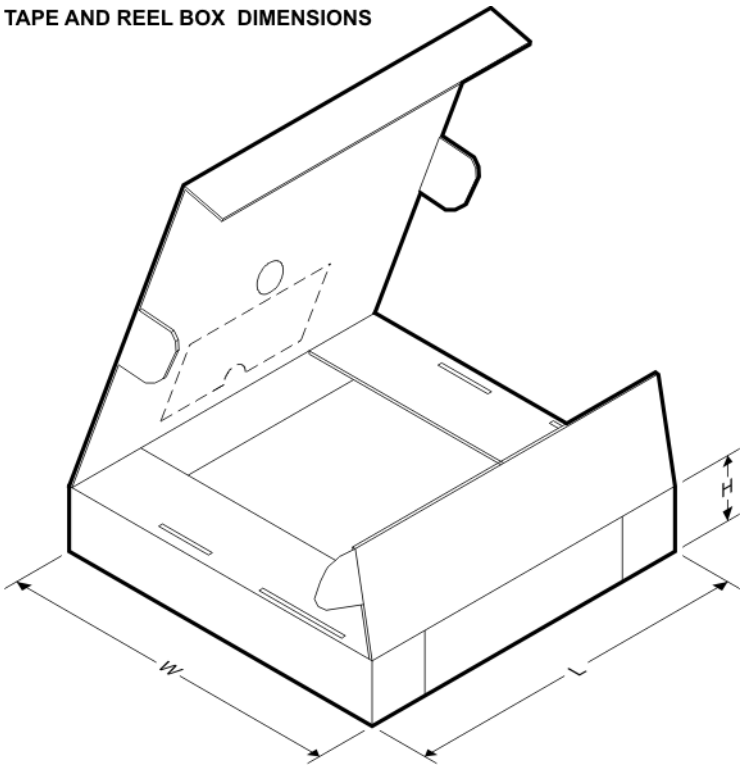
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC2272AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2274AMDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLC2274MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

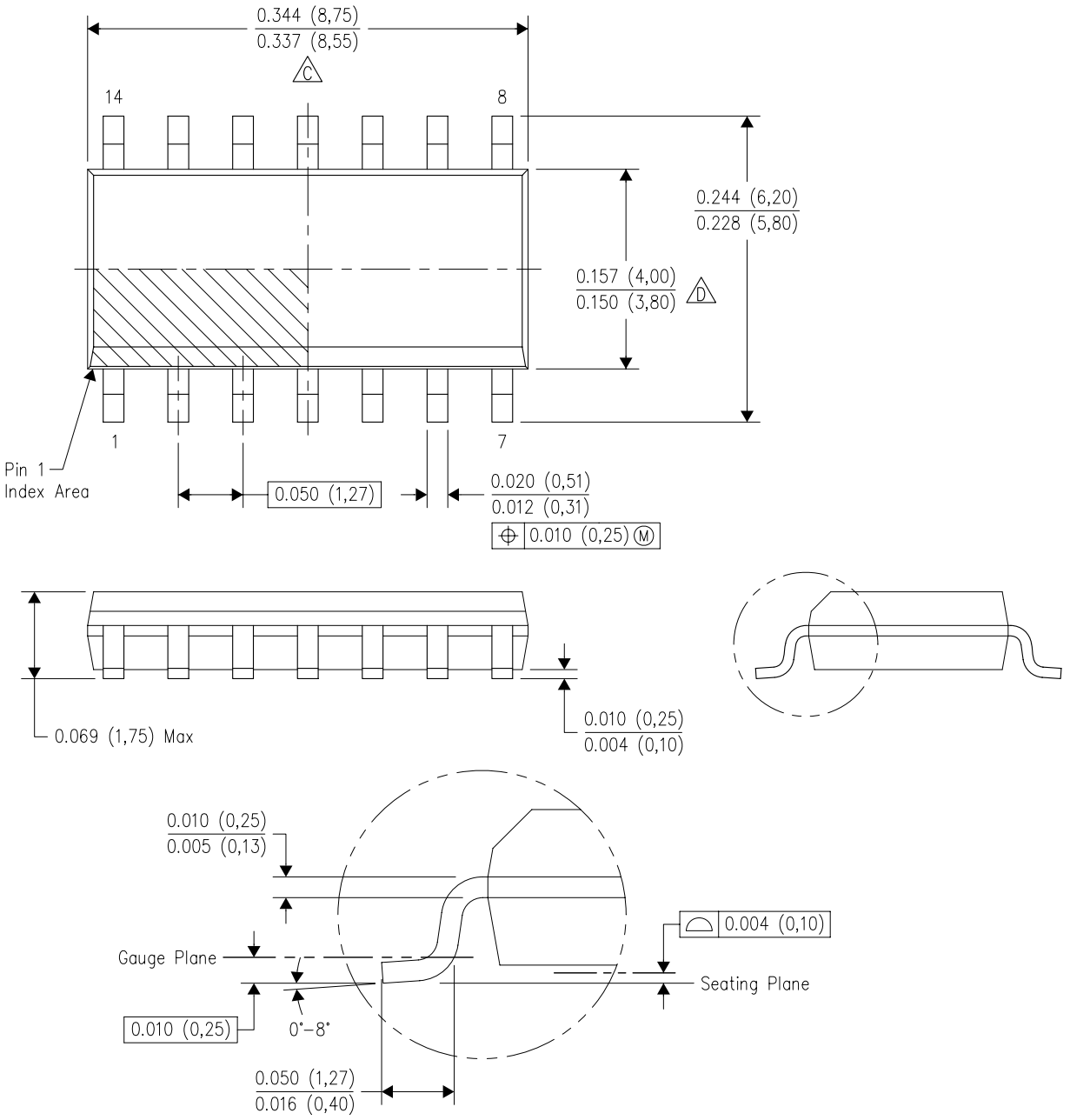
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC2272AMDREP	SOIC	D	8	2500	367.0	367.0	35.0
TLC2274AMDREP	SOIC	D	14	2500	333.2	345.9	28.6
TLC2274AMPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0
TLC2274MDREP	SOIC	D	14	2500	333.2	345.9	28.6
TLC2274MPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

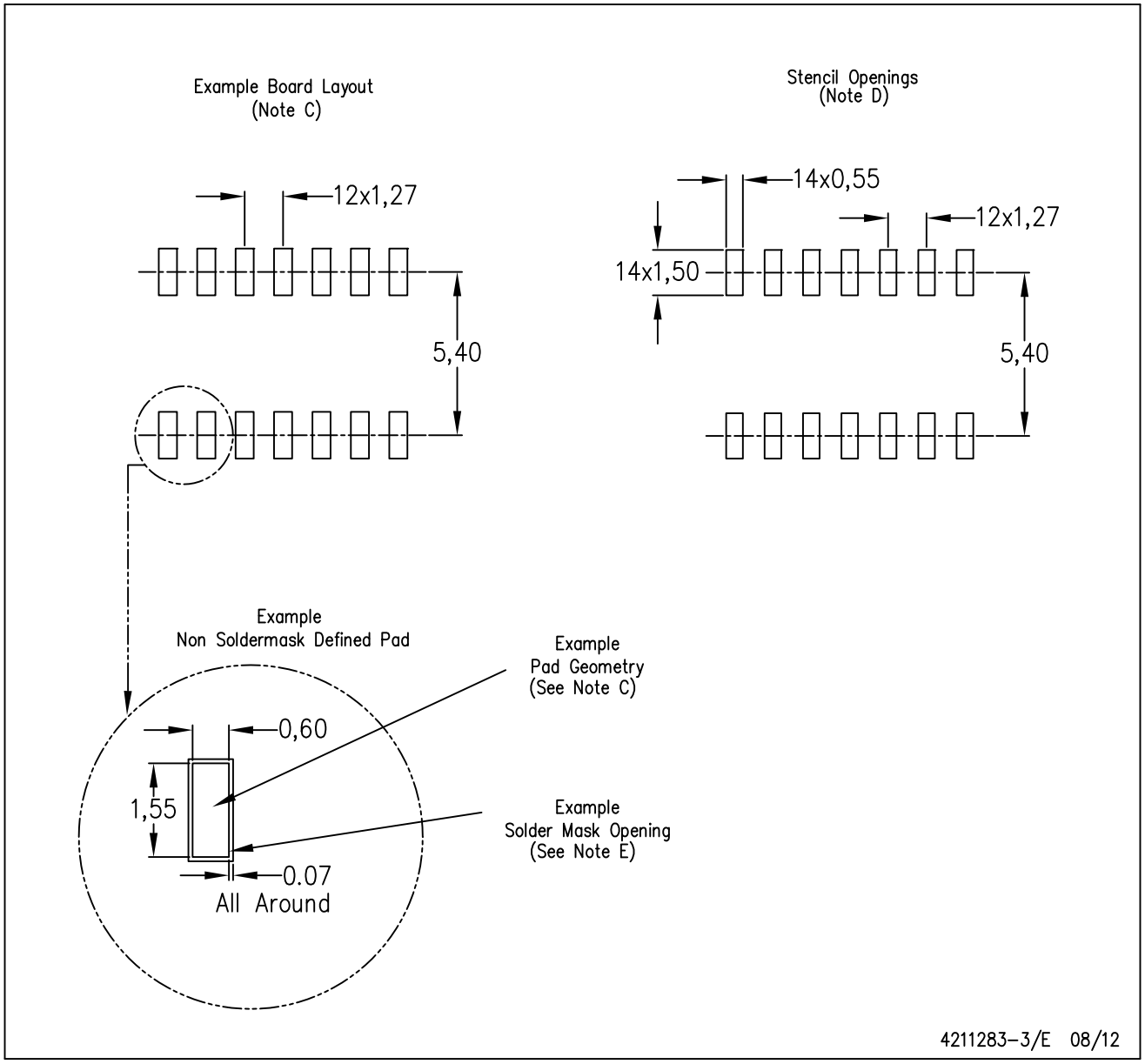
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

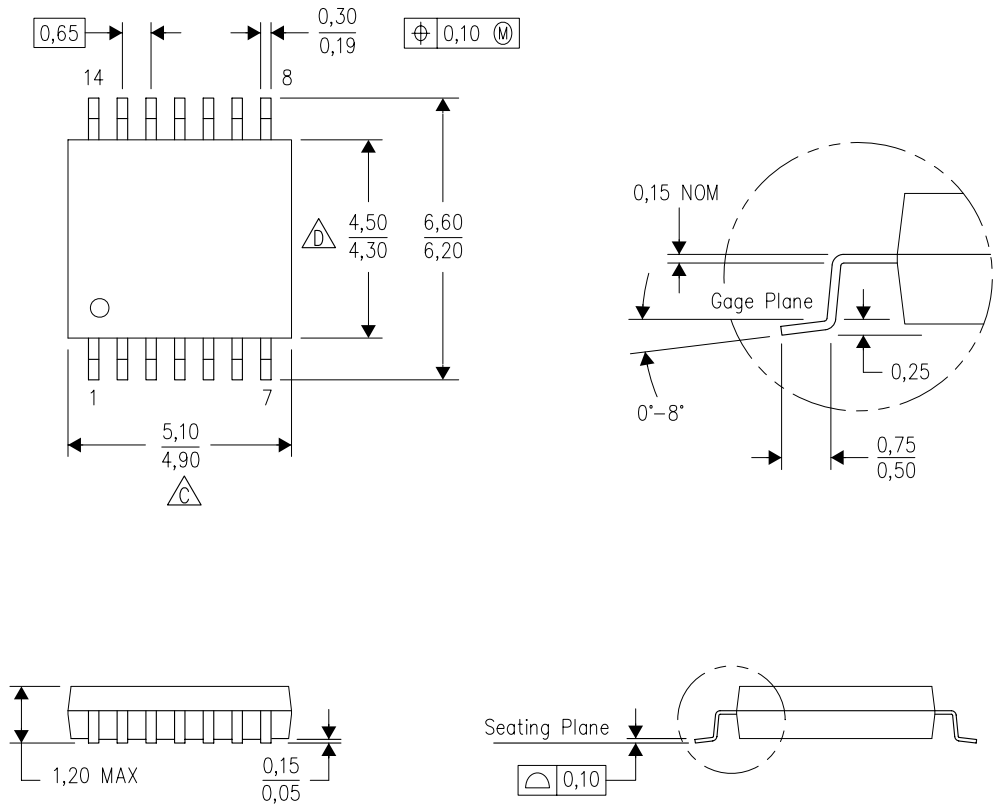
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

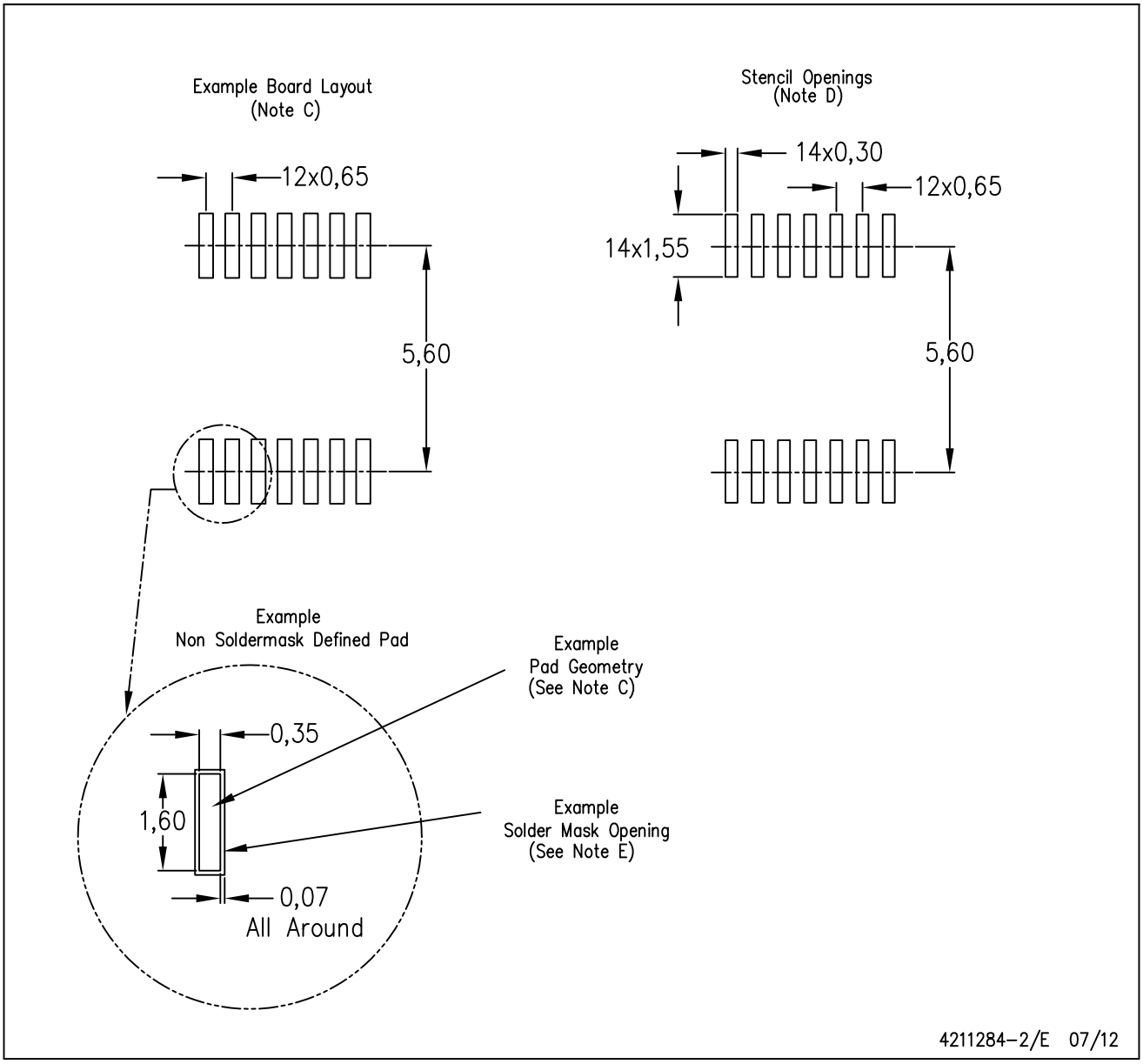
PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040064–3/G 02/11

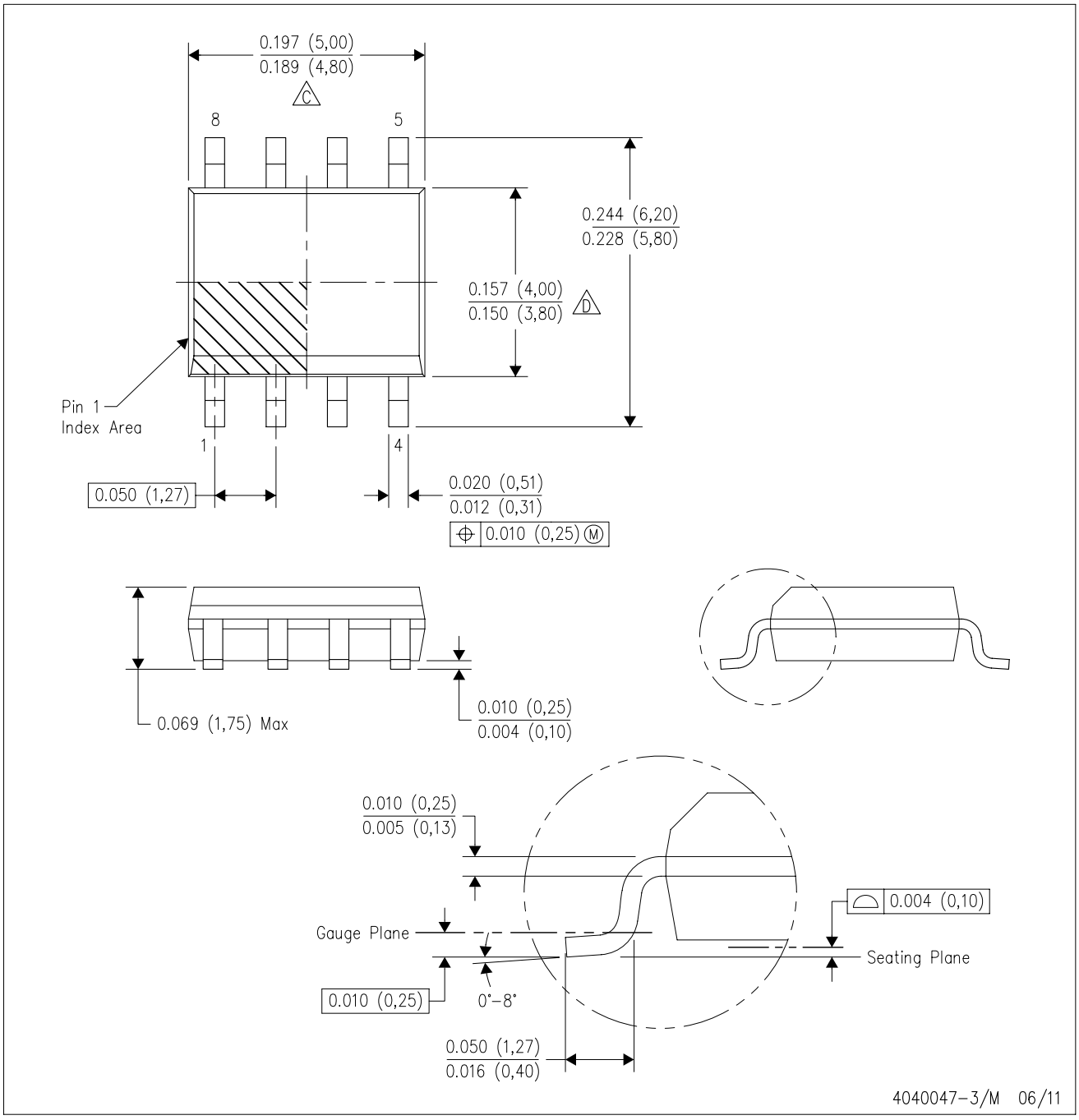
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G14) PLASTIC SMALL OUTLINE



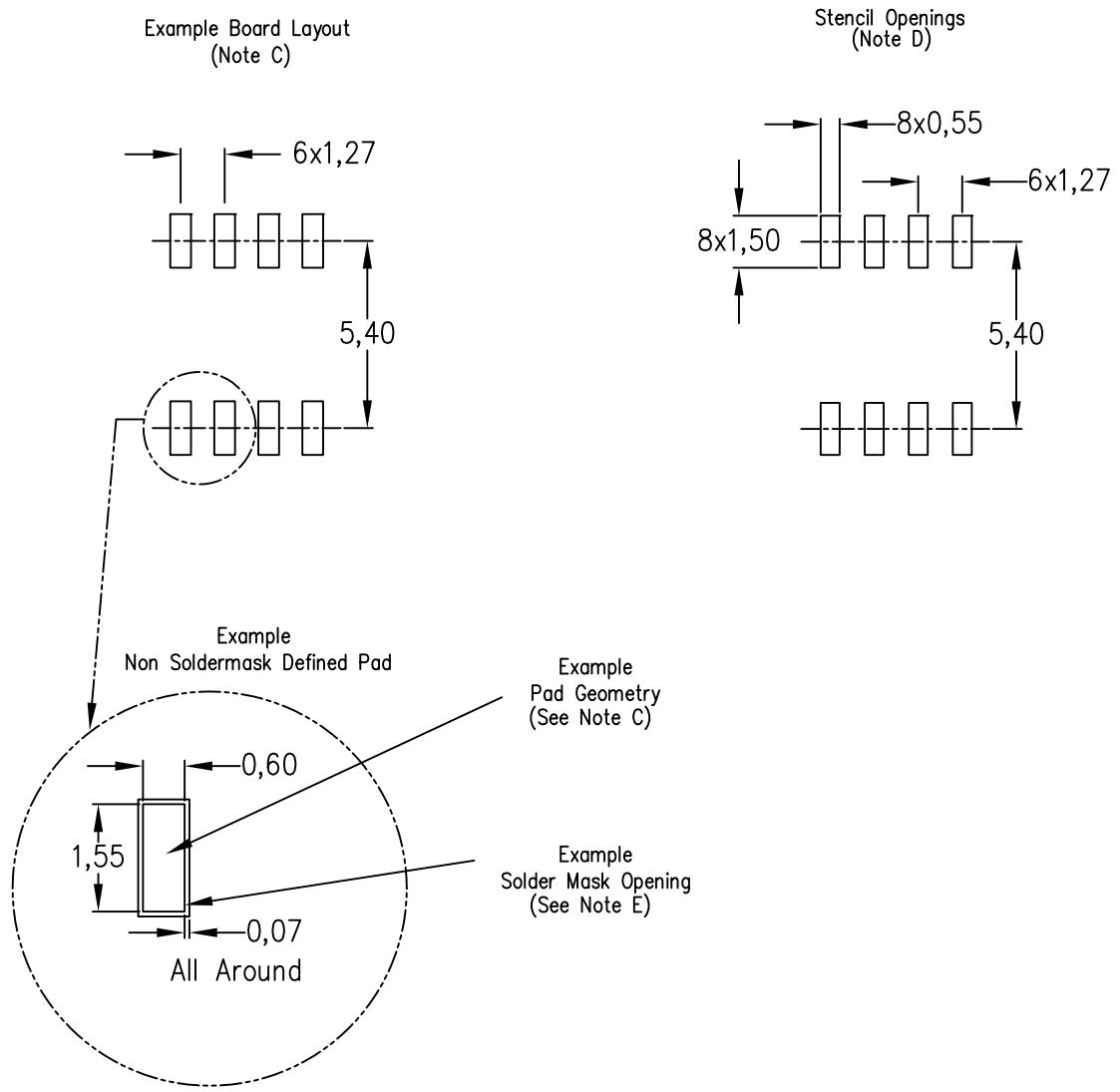
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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